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R8C/2D 群

I²C 总线控制程序

1. 概要

本资料说明了使用硬件控制 I²C 总线的程序和应用例。可应用于 EEPROM 的控制等。

2. 前言

在本资料中说明的应用例，适合以下单片机在下列条件下使用。

- 单片机：R8C/2D 群

和 R8C/2D 群有相同 SFR（外围设备控制寄存器）的其它 R8C/Tiny 系列也可以使用本程序。在使用本应用说明时必须进行充分的评价。

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3. 应用例的说明

I²C 总线接口是根据飞利浦公司 I²C 总线的数据传送格式进行串行通信。

本资料就 R8C/2D 群的单片机作为主器件在单主和多主时的 I²C 总线控制进行说明。

在本应用例中，如果主器件接受 $\overline{\text{INT0}}$ 中断请求就开始进行主发送，如果接受 $\overline{\text{INT1}}$ 中断就开始主接收。

(1) 主发送/接收模式（单主）

通过 $\overline{\text{INT0}}$ 、 $\overline{\text{INT1}}$ 中断请求开始主发送/接收。由于是在单主的状态下运行，所以不进行通过总线竞争的仲裁判定。结束发送/接收后，设定为从属接收模式并等待下一个发送/接收请求的状态。

(2) 从属发送/接收模式

在从属接收模式的状态下等待数据直到从主器件接收数据。如果开始条件后的第 1 帧数据和从属地址匹配，就开始发送/接收。

I²C 总线通信的数据传送例如图 1 所示。

发送时，主器件输出发送时钟和发送数据，从属器件返回应答。接收时，主器件输出发送时钟，接收来自从属器件的数据并返回应答。接收完最终数据后返回 NACK，通知从属器件通信结束。

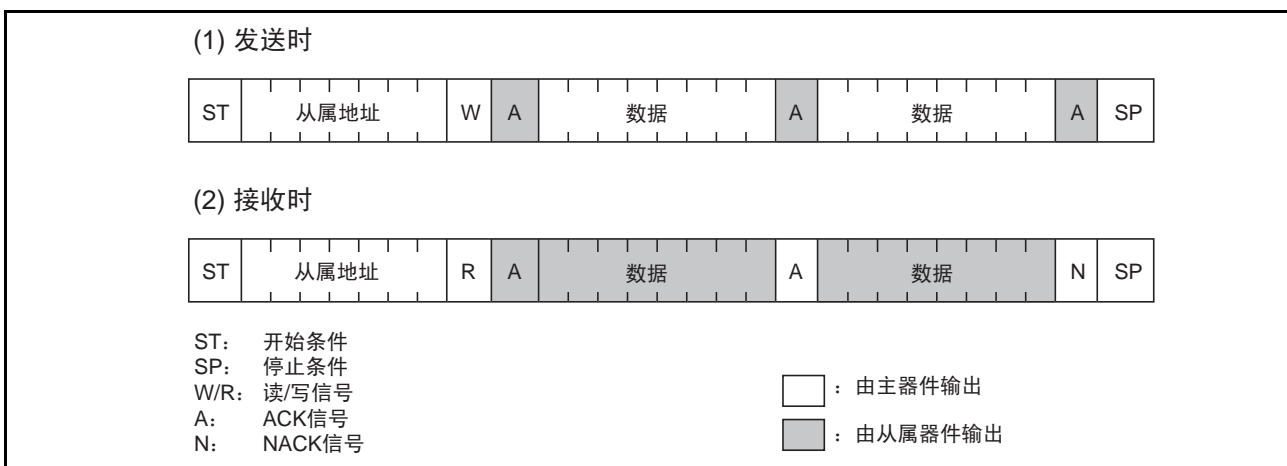


图 1 I²C 总线通信的数据传送

(3) 主发送/接收模式和从属发送/接收模式（多主）

是指将多个主器件连接到总线的状态。在从属接收模式下等待直到接受主发送/接收请求。一旦接受了主发送/接收请求就开始主发送。此时，如果其它器件开始主发送，就会因产生总线竞争而进行仲裁判定。赢得仲裁时，继续主发送。仲裁失败时，变成从属接收模式。

从属接收模式时，由主器件接收数据，如果开始条件的第1帧数据与从属地址匹配，就开始从属发送/接收。

多主总线的连接图如图2所示。

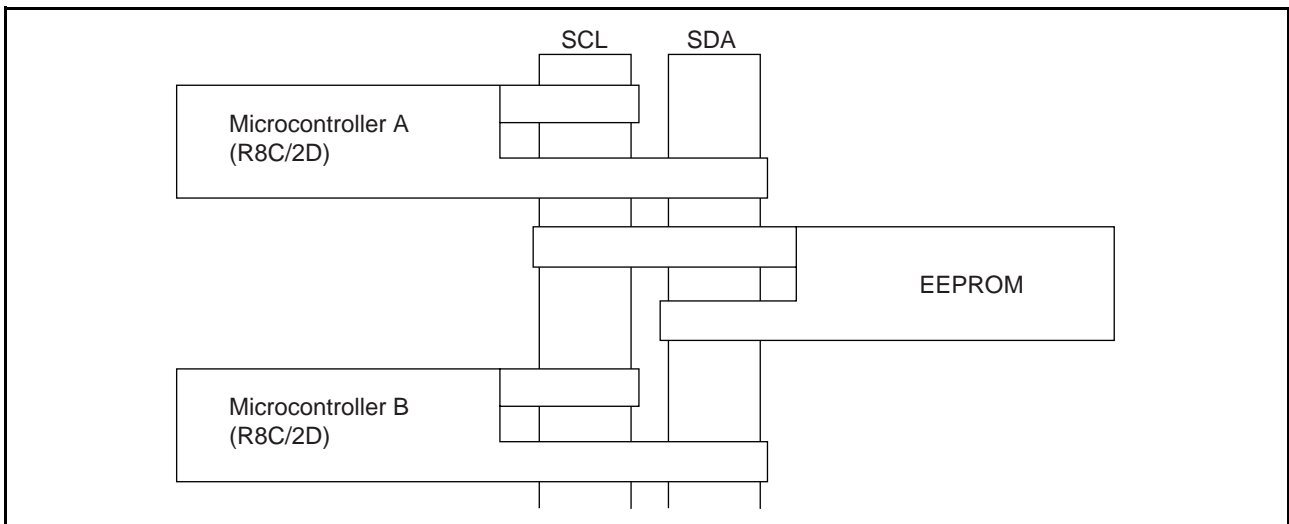


图2 多主总线的连接图

3.1 使用的引脚

表1 使用的引脚和功能

| 引脚名 | 输入/输出 | 功能 |
|----------|-------|-----------|
| P3_5/SCL | 输入/输出 | 输入/输出串行时钟 |
| P3_4/SDA | 输入/输出 | 输入/输出串行数据 |

3.2 使用的存储器

表2 使用的存储器

| 使用的存储器 | 大小 | | | 备注 |
|----------|---------------|-------|--------------|--|
| | Single master | Slave | Multi master | |
| ROM | 583字节 | 313字节 | 881字节 | 仅限main.c模块内 |
| RAM | 9字节 | 10字节 | 18字节 | 仅限main.c模块内 |
| 用户堆栈的最大值 | 23字节 | 16字节 | 26字节 | main函数: 7字节 sfr_init函数: 3字节 i ² c_communication函数: 16字节(Single master) 9字节(Slave) 19字节(Multi master) |
| 中断堆栈的最大值 | 0字节 | | | 未使用 |

Single master: 主发送/接收模式 (单主时)

Slave: 从属发送/接收模式

Multi master: 主发送/接收模式和从属发送/接收模式 (多主)

表3 使用的RAM和定义 (主发送/接收模式, 单主时)

| 符号名 | 型号 | 大小 | 内容 |
|-------------|---------------|-----|-----------|
| _count | unsigned char | 1字节 | 传送次数 |
| _data | unsigned char | 3字节 | 发送数据 |
| _data_store | unsigned char | 3字节 | 接收数据 |
| _mode | unsigned char | 1字节 | 发送/接收模式 |
| _info | unsigned char | 1字节 | 发送/接收错误标志 |

表4 使用的RAM和定义 (从属发送/接收模式)

| 符号名 | 型号 | 大小 | 内容 |
|-------------|---------------|-----|------|
| _count | unsigned char | 1字节 | 传送次数 |
| _data_set | unsigned char | 3字节 | 发送数据 |
| _data_store | unsigned char | 3字节 | 接收数据 |
| _address | unsigned char | 1字节 | 从属地址 |
| _dummy | unsigned char | 1字节 | 虚读 |
| _dummy1 | unsigned char | 1字节 | 虚读1 |

表5 使用的RAM和定义（主发送/接收模式和从属发送/接收模式，多主时）

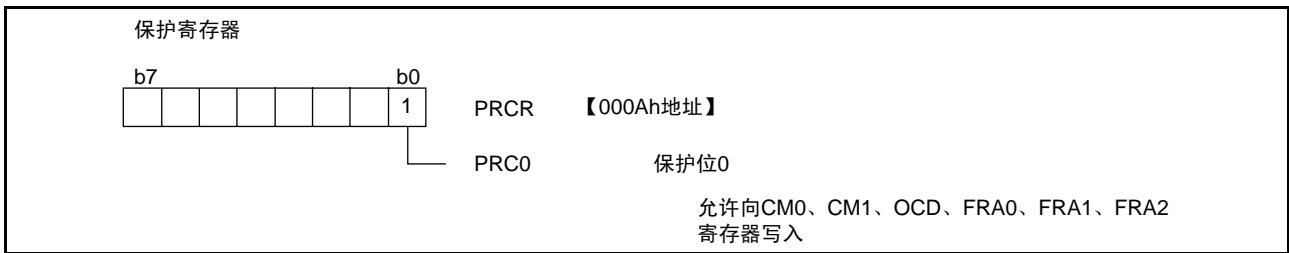
| 符号名 | 型号 | 大小 | 内容 |
|---------------|---------------|-----|------------------|
| _count | unsigned char | 1字节 | 传送次数 |
| _m_send_data | unsigned char | 3字节 | 发送数据（主发送/接收模式时） |
| _m_data_store | unsigned char | 3字节 | 接收数据（主发送/接收模式时） |
| _s_send_data | unsigned char | 3字节 | 发送数据（从属发送/接收模式时） |
| _s_data_store | unsigned char | 3字节 | 接收数据（从属发送/接收模式时） |
| _mode | unsigned char | 1字节 | 发送/接收模式 |
| _info | unsigned char | 1字节 | 发送/接收错误标志 |
| _address | unsigned char | 1字节 | 从属地址 |
| _dummy | unsigned char | 1字节 | 虚读 |
| _dummy1 | unsigned char | 1字节 | 虚读1 |

4. 关于设定方法

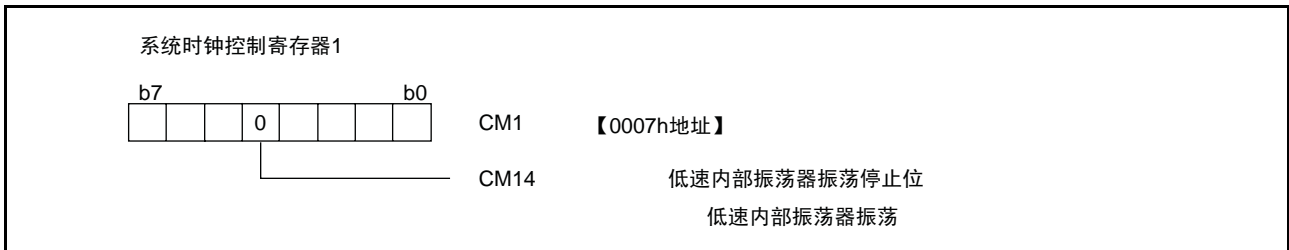
为实现“3. 应用例的说明”的初始设定步骤和设定值如下所示。各寄存器的详细情况请参照“R8C/2D 群硬件手册”。

4.1 系统时钟的设定

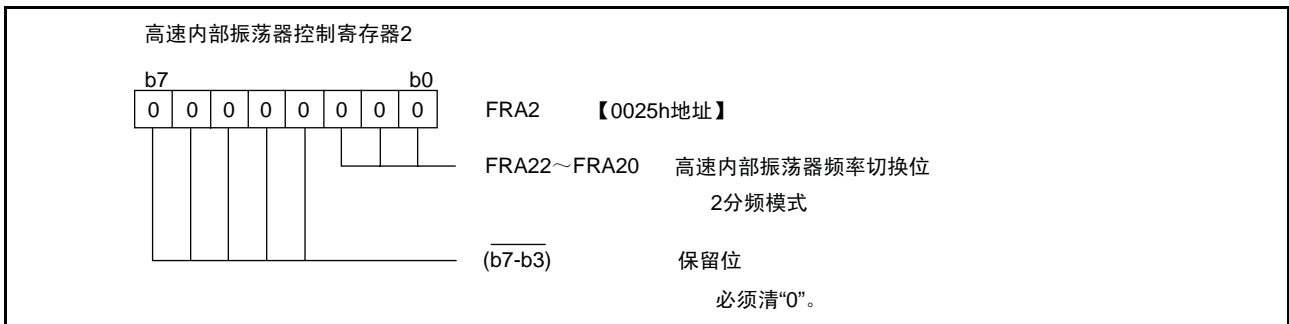
(1) 允许向CM0、CM1、OCD、FRA0、FRA1、FRA2寄存器写入。



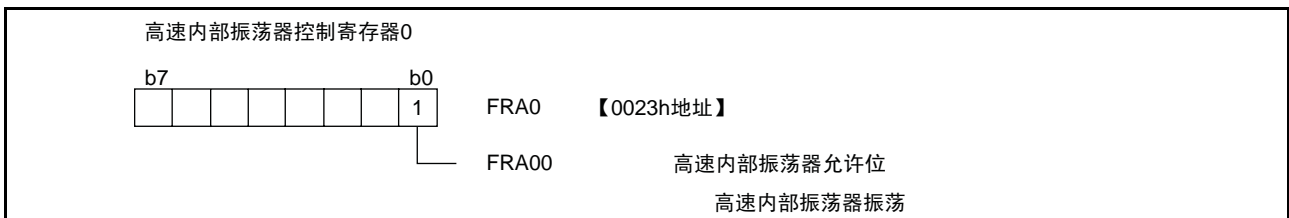
(2) 使低速内部振荡器产生振荡。



(3) 设定高速内部振荡器时钟分频比。

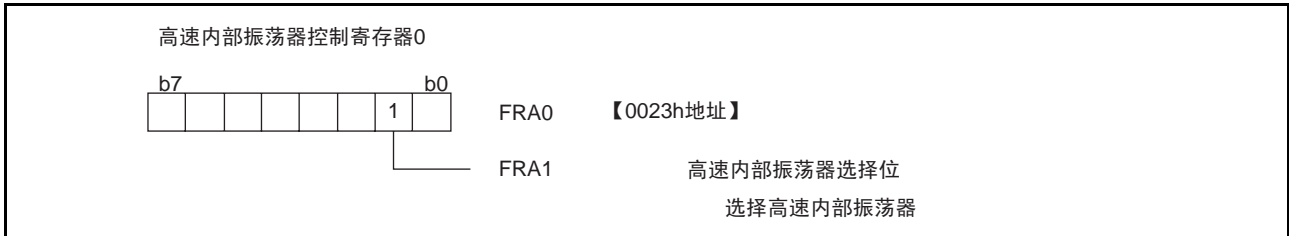


(4) 使高速内部振荡器产生振荡。



(5) 进行振荡稳定等待。

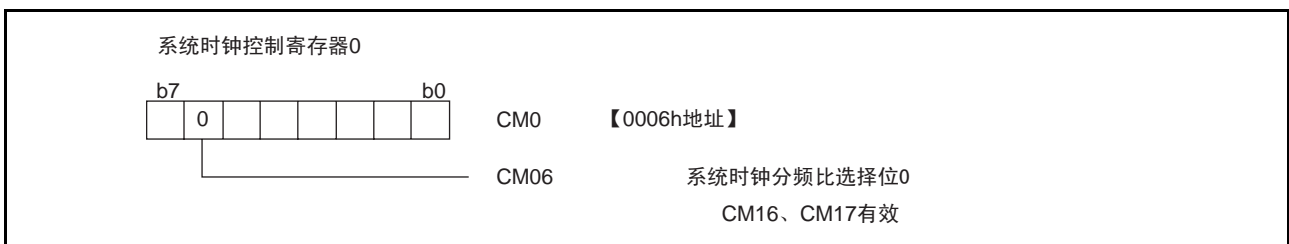
(6) 选择高速内部振荡器。



(7) 设定系统时钟分频比选择位1。



(8) 设定系统时钟分频比选择位0。

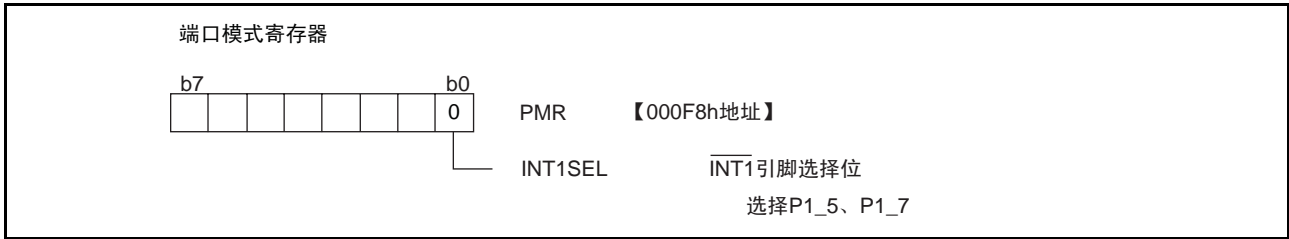


(9) 禁止向CM0、CM1、OCD、FRA0、FRA1、FRA2寄存器写入。

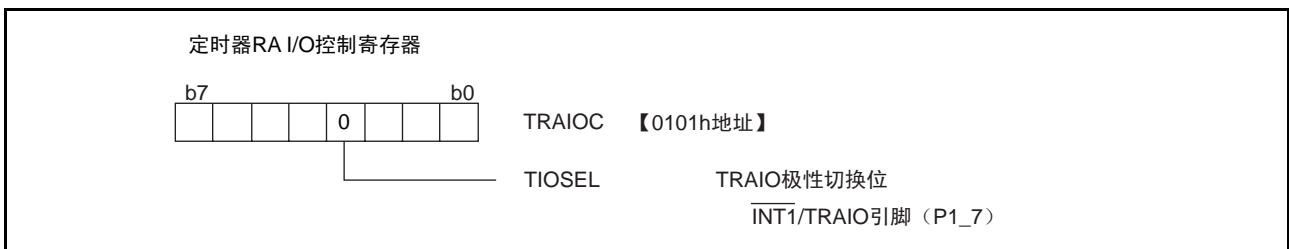


4.2 $\overline{\text{INT0}}$ 中断请求、 $\overline{\text{INT1}}$ 中断请求的设定

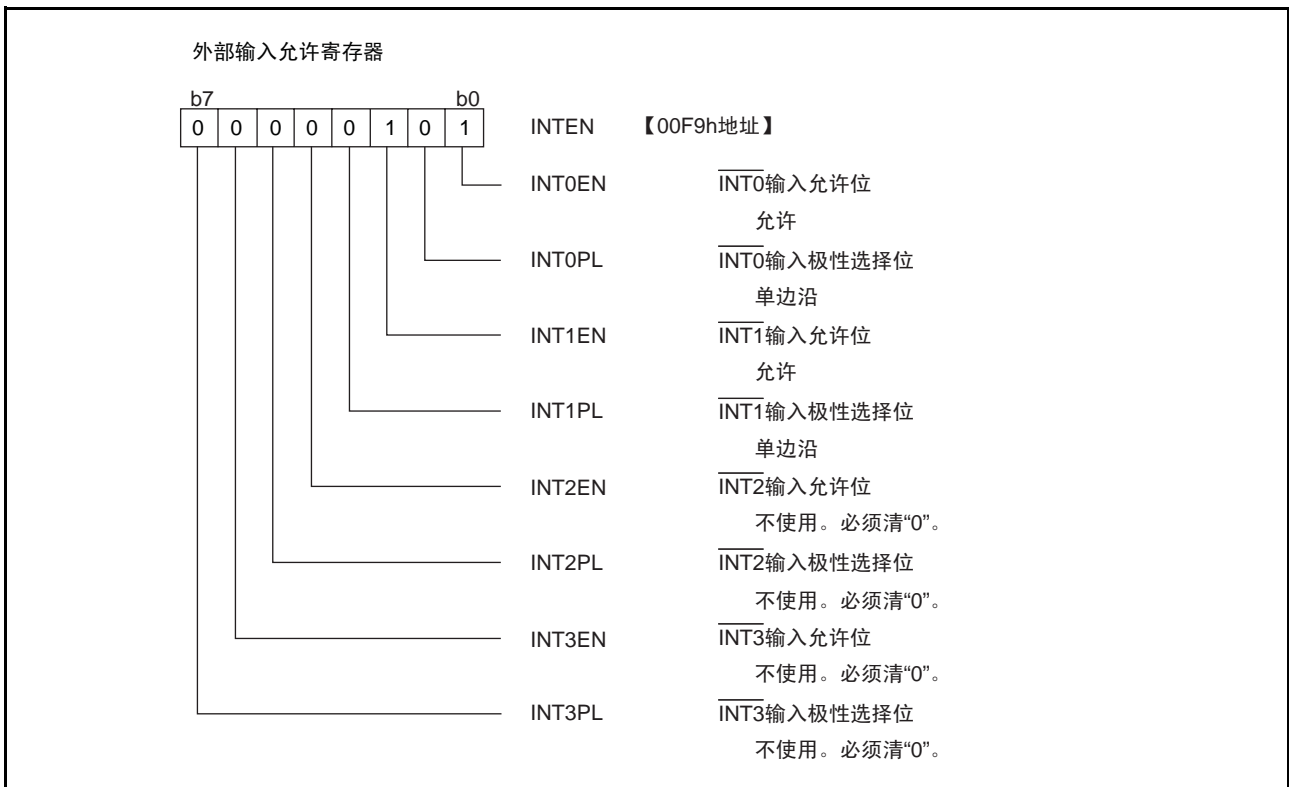
(1) 将 $\overline{\text{INT1}}$ 引脚选择为P1_5、P1_7。



(2) 将 $\overline{\text{INT1}}$ 引脚选择为P1_7。



(3) 设定外部输入允许寄存器。

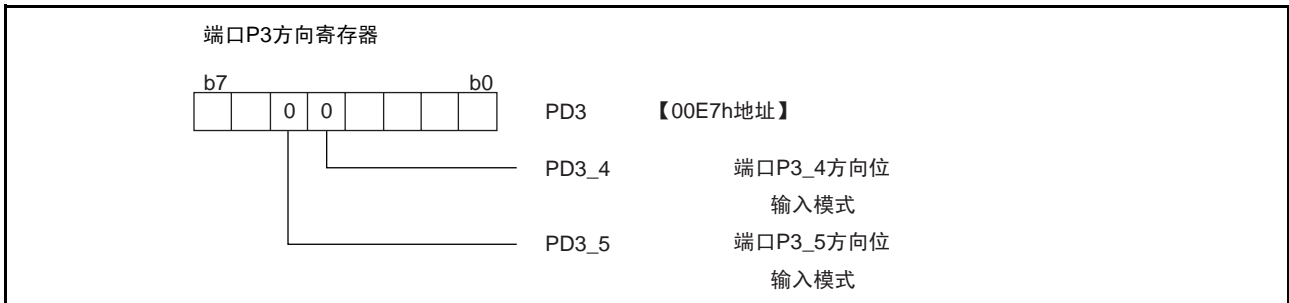


4.3 主发送/接收模式的设定

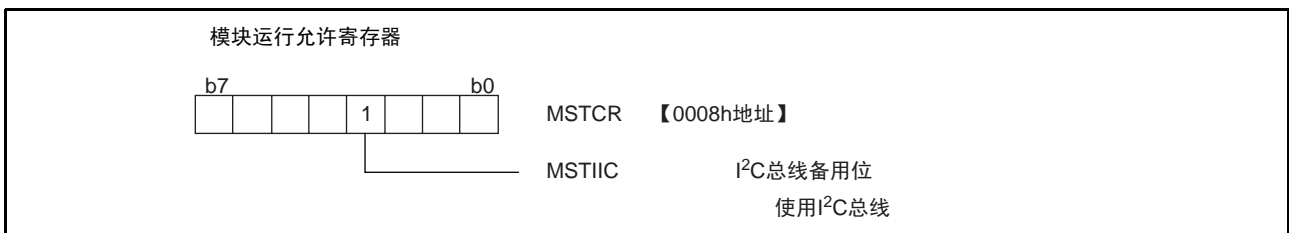
4.3.1 初始设定

设定为可进行传送状态，并设定传送时钟和传送格式。

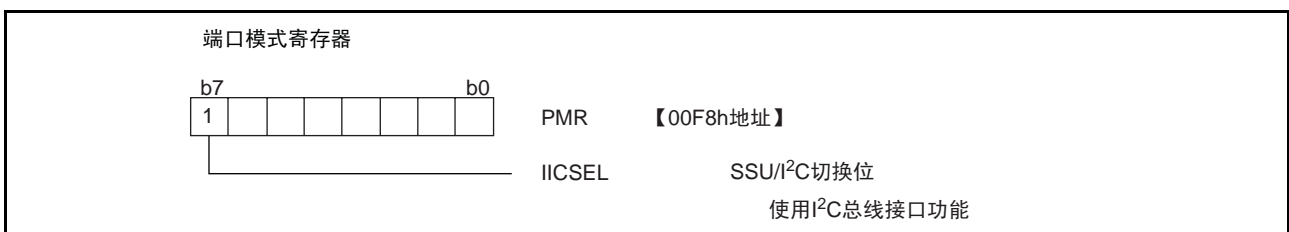
(1) 将端口P3_4方向位、端口P3_5方向位设定为输入模式。



(2) 设定I²C总线备用位。



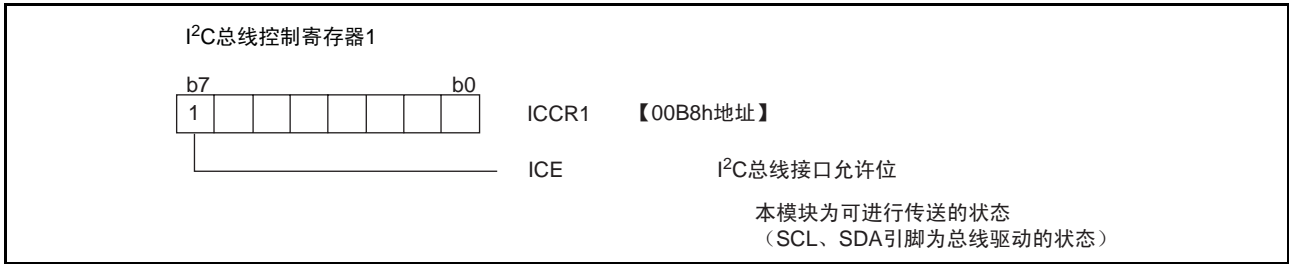
(3) 设定SSU/I²C切换位。



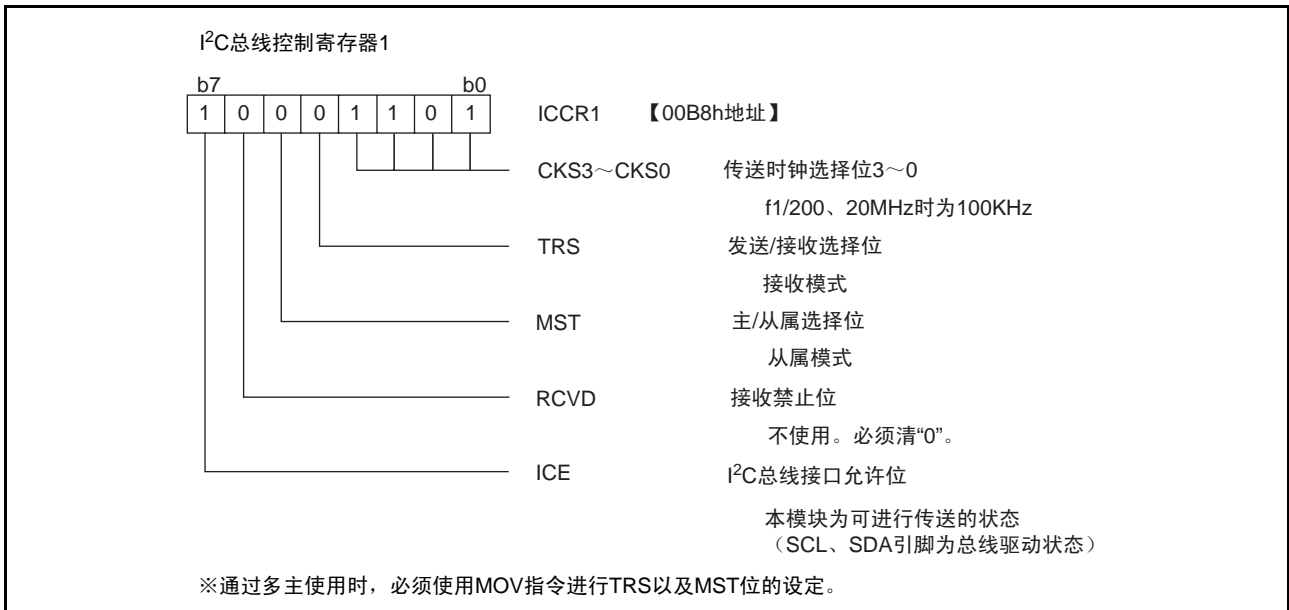
(4) 初始化ICSR寄存器的STOP位。



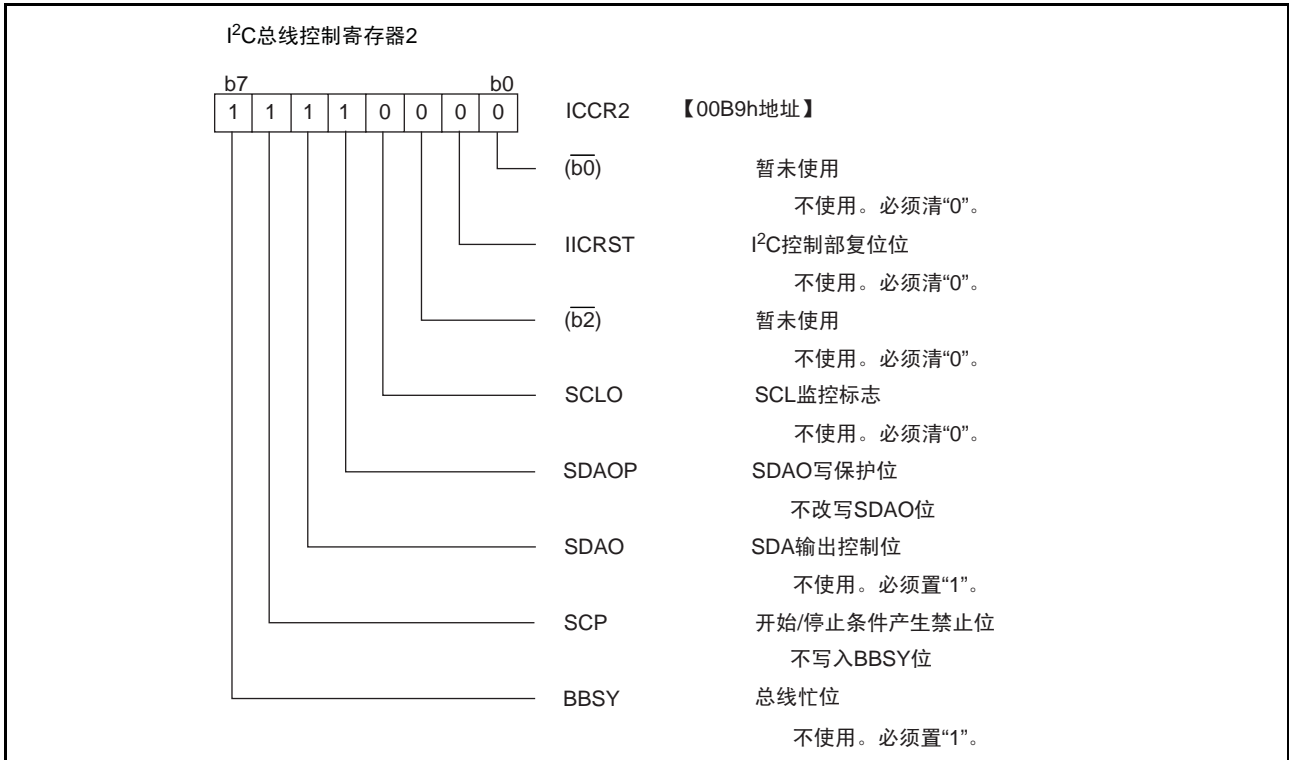
(5) 将I²C总线设定为可进行传送状态。



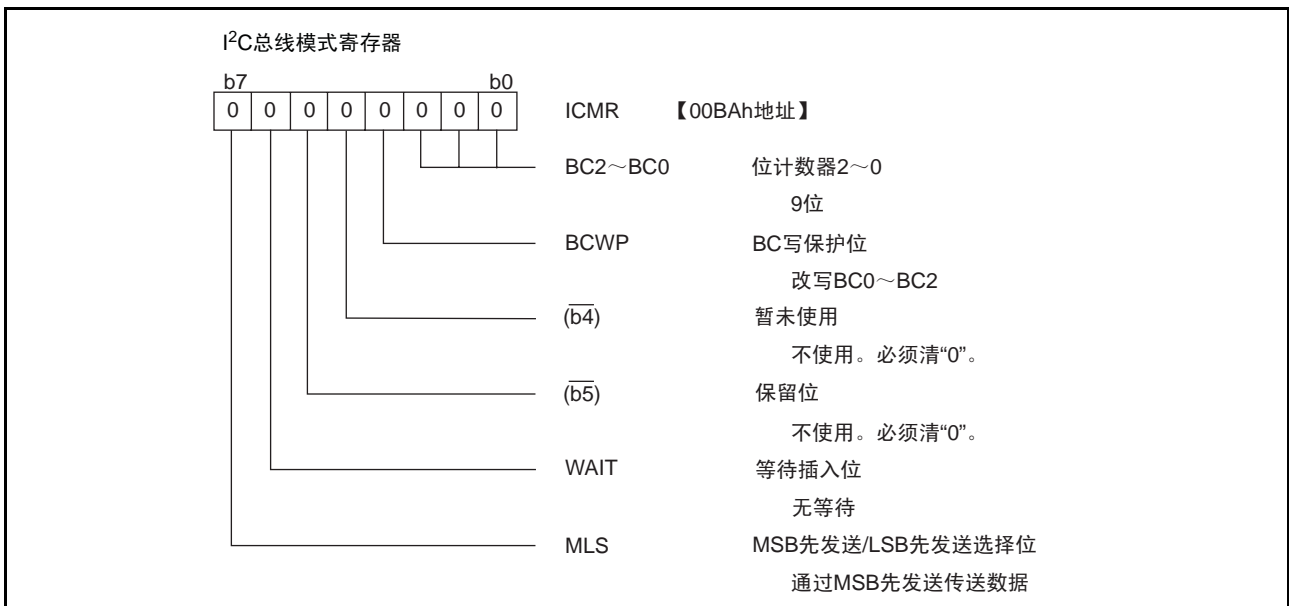
(6) 设定I²C总线控制寄存器1。



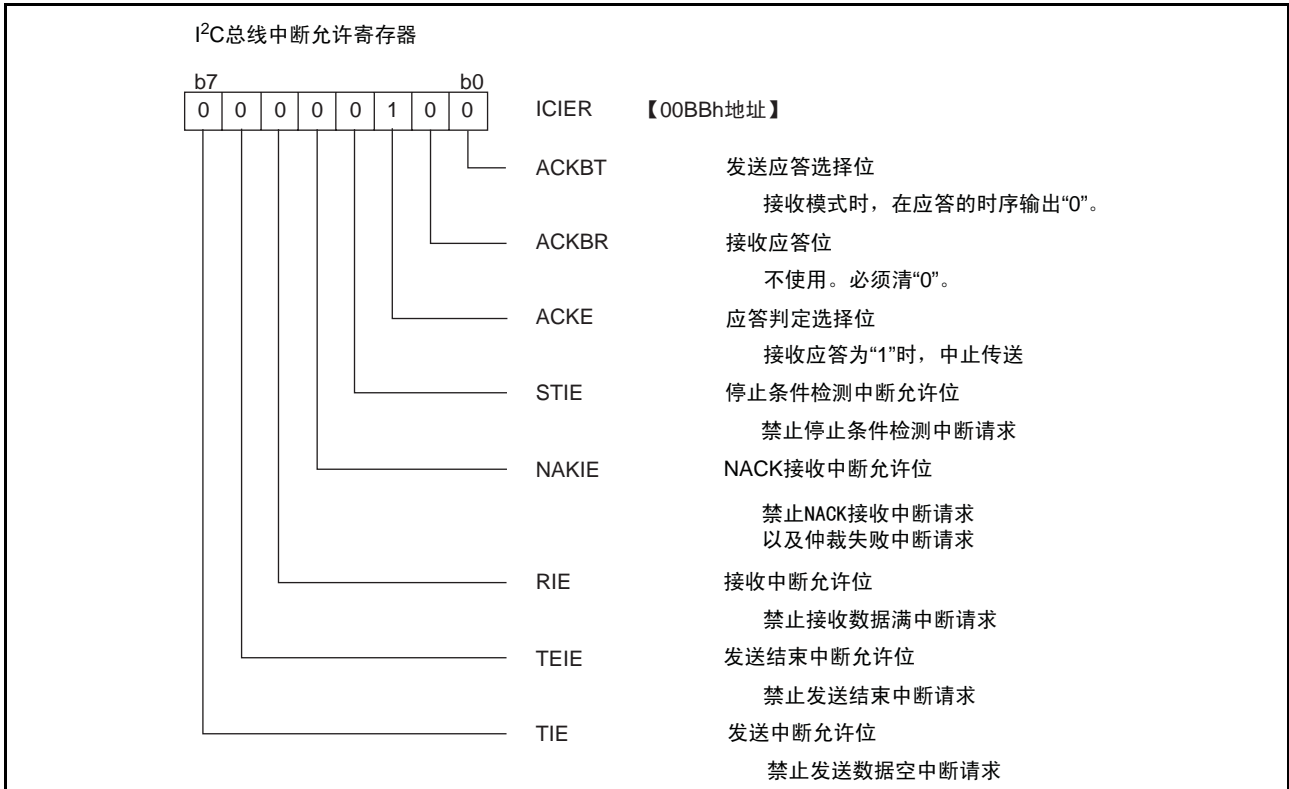
(7) 设定 I²C 总线控制寄存器 2。



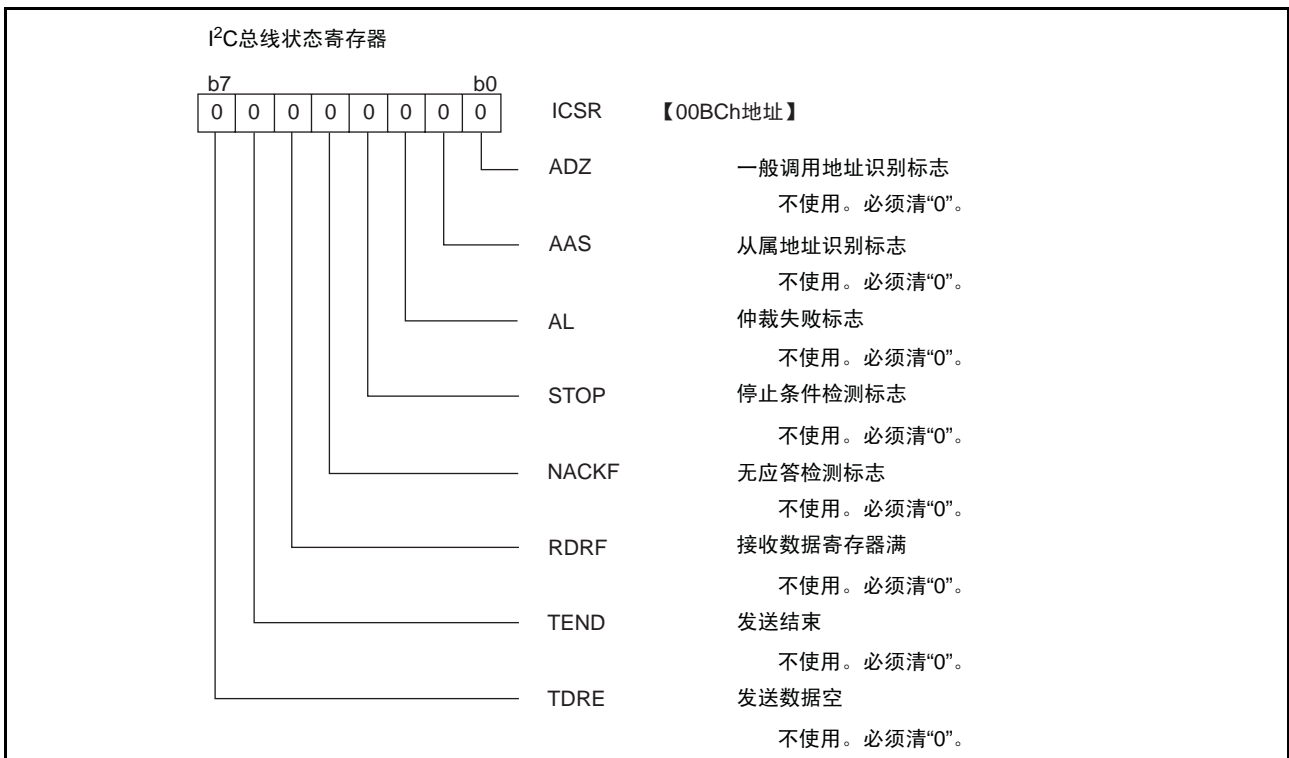
(8) 设定 I²C 总线模式寄存器。



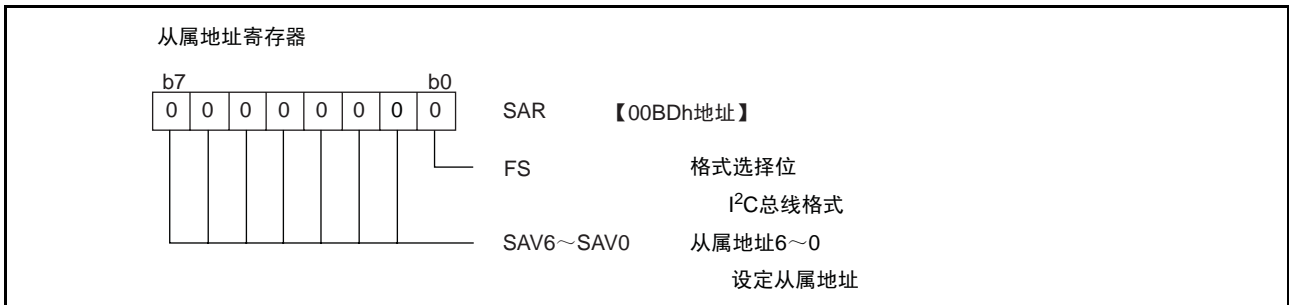
(9) 设定 I²C 总线中断允许寄存器。



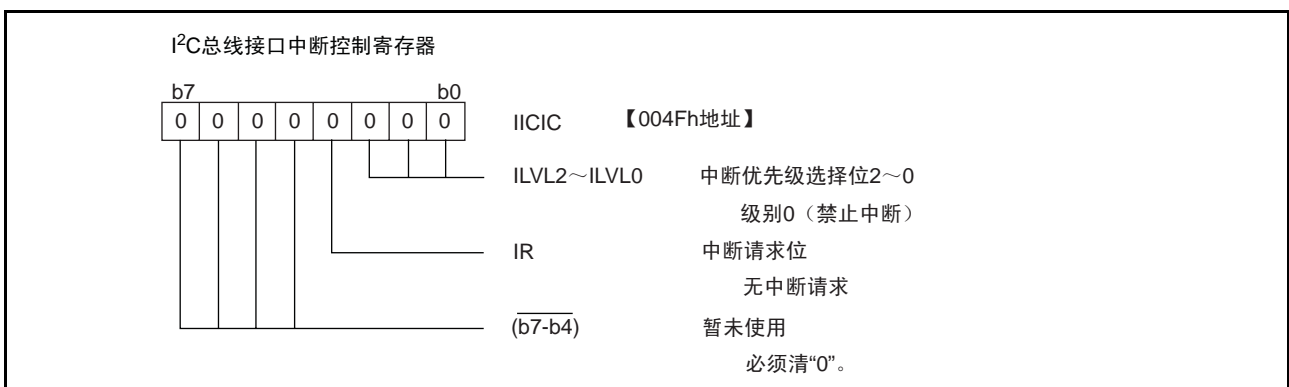
(10) 设定 I²C 总线状态寄存器。



(11) 设定从属地址寄存器。



(12) 设定I²C总线接口中断控制寄存器。



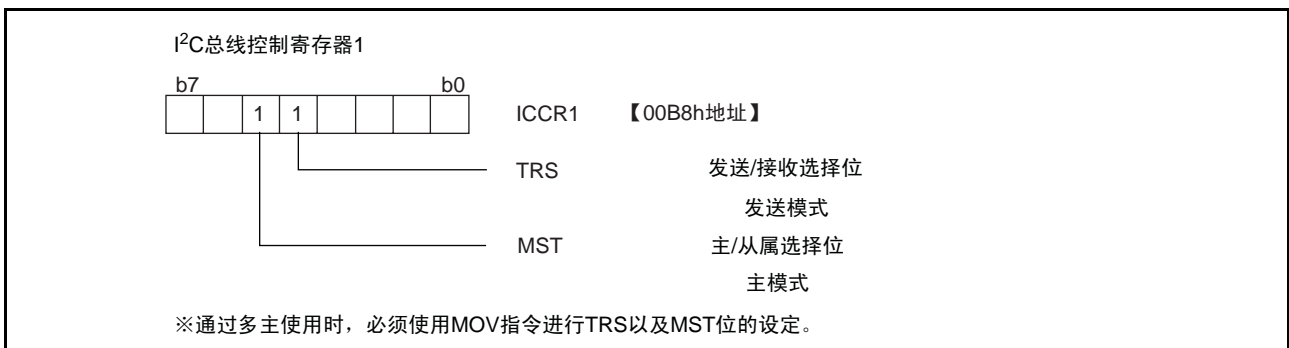
4.3.2 主发送

(1) 初始化ICSR寄存器的STOP位。

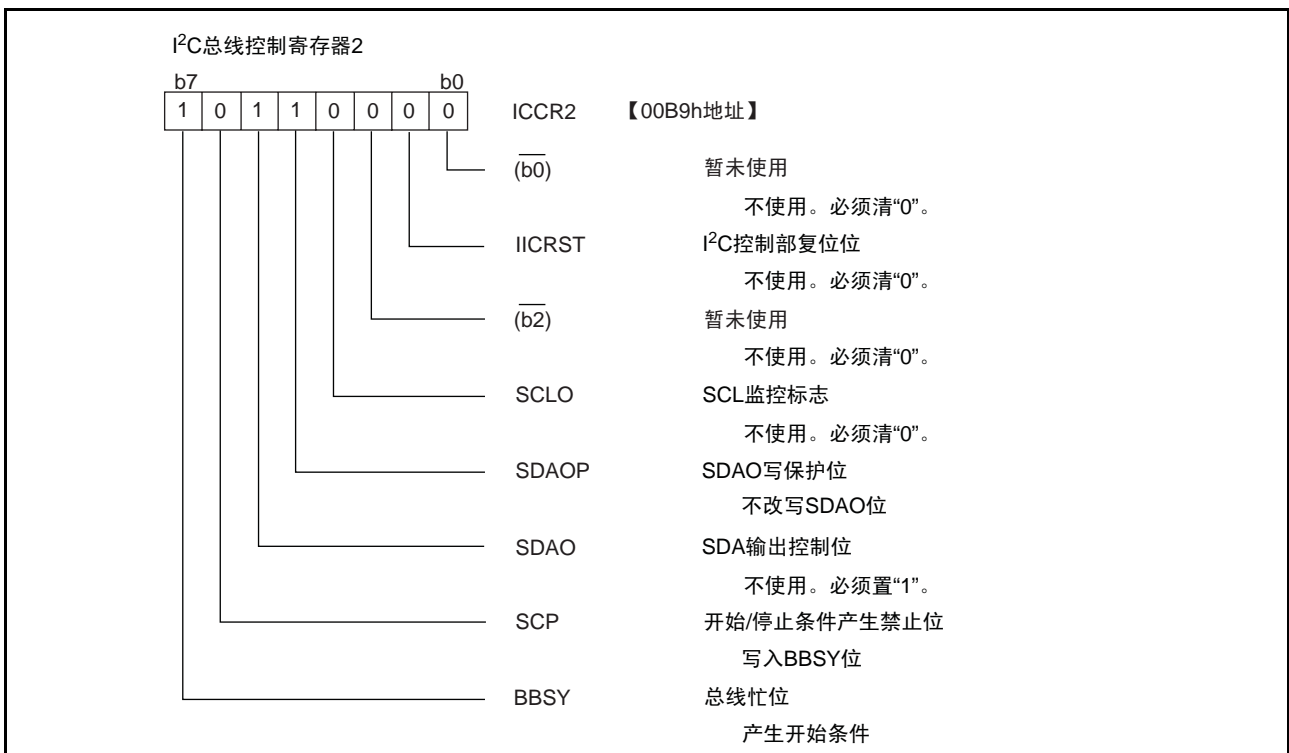


(2) 必须通过读ICCR2寄存器的BBSY位，确认总线为开放状态。

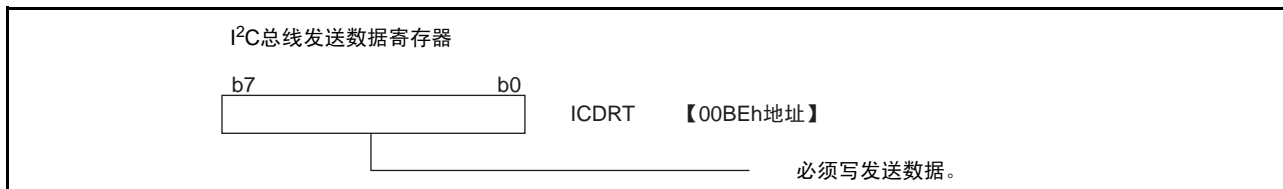
(3) 将ICCR1寄存器的TRS、MST位设定为主发送模式。



(4) 必须使用MOV指令写BBSY=1和SCP=0（产生开始条件）。由此产生开始条件。



(5) 必须在确认 ICSR 寄存器的 TDRE 位为 “1” 后，向 ICDRT 寄存器写发送数据（第 1 字节为从属地址和 R/W 的数据）。此时 TDRE 位自动清 “0”，从 ICDRT 寄存器向 ICDRS 寄存器传送数据后，TDRE 位又变为 “1”。



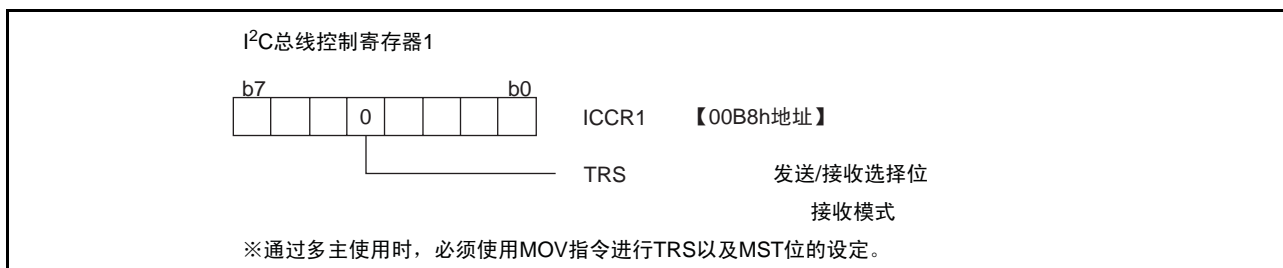
(6) 在 TDRE 位为 “1” 的状态下结束 1 字节发送，ICSR 寄存器的 TEND 位在发送时钟的第 9 个时钟的上升沿变为 “1”。必须在读 ICIER 寄存器的 ACKBR 位并确认已选择从属器件后，向 ICDRT 寄存器写第 2 字节的数据。因为 ACKBR 位为 “1” 时不能识别从属器件，所以必须产生停止条件。

(7) 关于第 2 字节以后的发送数据，每当 TDRE 位变为 “1” 时，必须向 ICDRT 寄存器写数据。

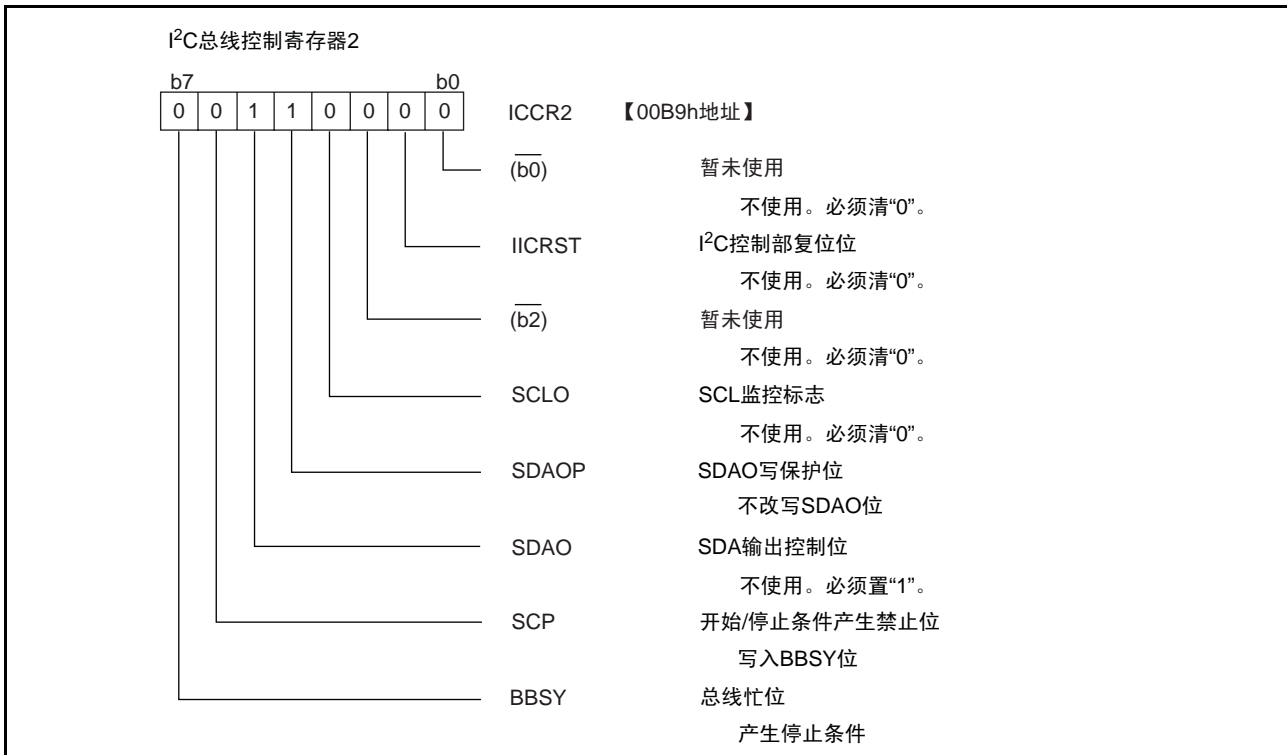
(8) 将发送的字节数写入 ICDRT 寄存器后，在 TDRE 位为 “1” 的状态下，等待 TEND 位变为 “1”。或者，在 ICIER 寄存器的 ACKE 位为 “1”（接收应答为 “1” 时，中止传送）的状态下，等待来自接收器件的 NACK（ICSR 寄存器的 NACKF = 1）。

以下是停止条件的产生处理顺序。

(9) 将 ICCR1 寄存器的 TRS 位设定为接收模式。



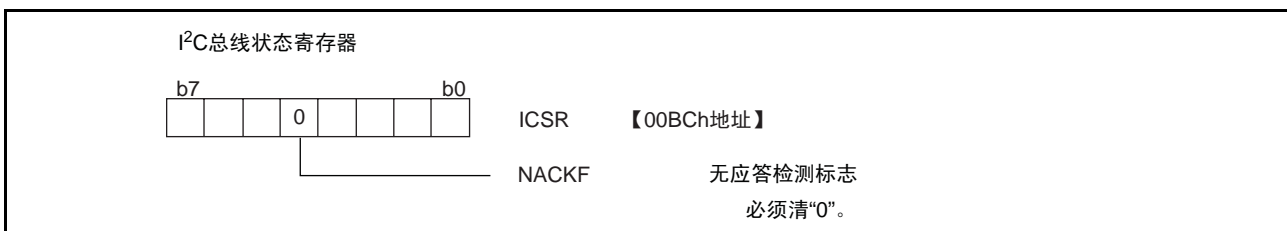
(10) 必须使用MOV指令写BBSY=0和SCP=0（产生停止条件）。由此产生停止条件。



(11) 将ICSR寄存器的TEND位清“0”。



(12) 将ICSR寄存器的NACKF位清“0”。

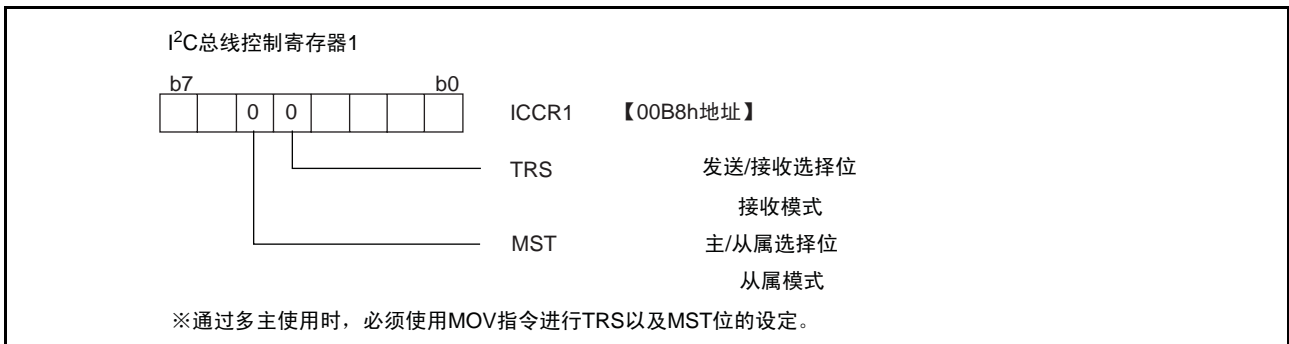


(13) 通过读ICSR寄存器的STOP位，确认已检测到停止条件。

(14) 将 ICSR 寄存器的 STOP 位清 “0”。



(15) 将 ICCR1 寄存器的 TRS、MST 位设定为从属接收模式。



4.3.3 主接收

(1) 将 ICSR 寄存器的 TEND 位清 “0”。



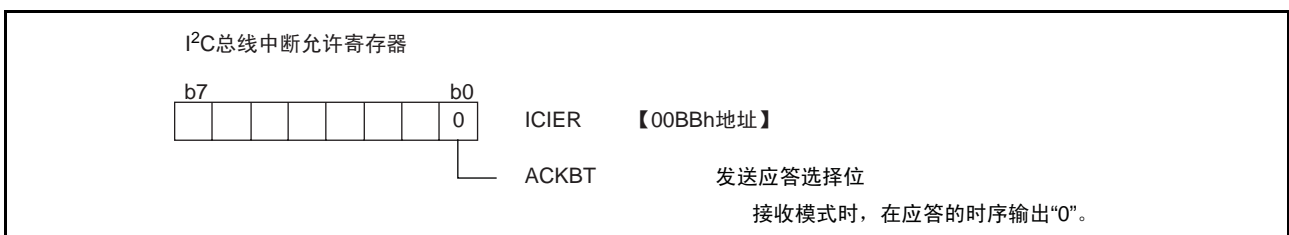
(2) 将 ICCR1 寄存器的 TRS 位设定为接收模式。



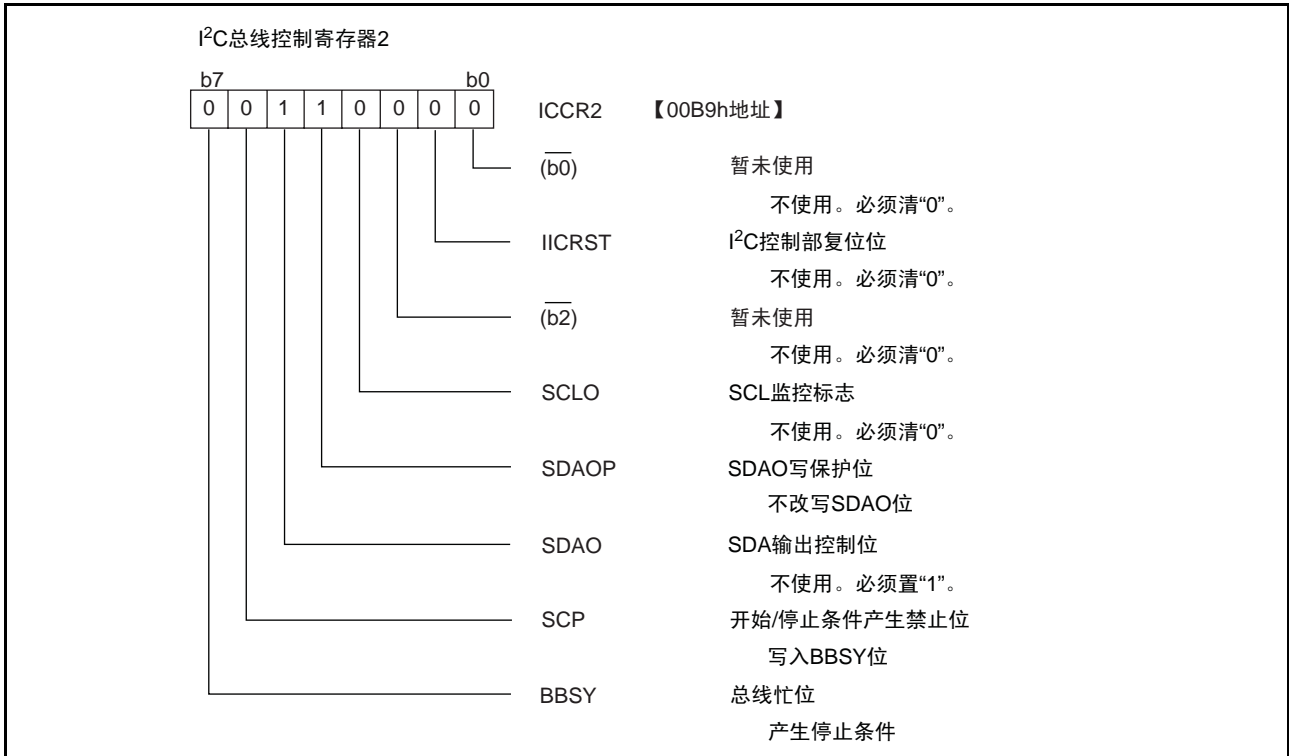
(3) 将 ICSR 寄存器的 TDRE 位清 “0”。



(4) 将 ICIER 寄存器的 ACKBT 位设定为 “0”。



(10) RDRF位在接收时钟的第9个时钟的上升沿变为“1”。产生停止条件。



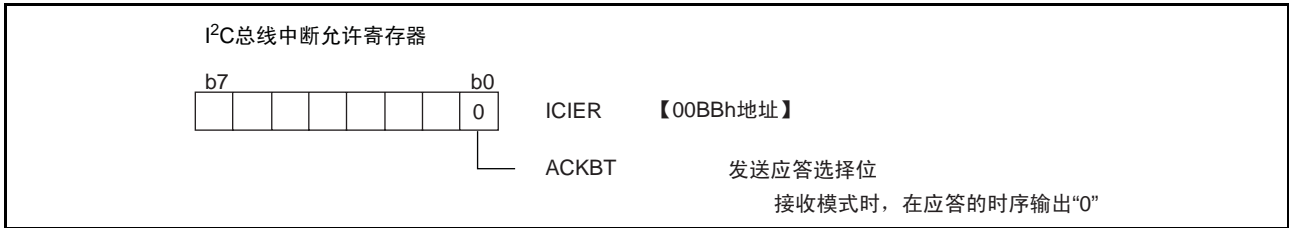
(11) 必须在ICSR寄存器的STOP位为“1”时读ICDRR寄存器。此后，将RCVD位清“0”（继续下一个接收运行）。



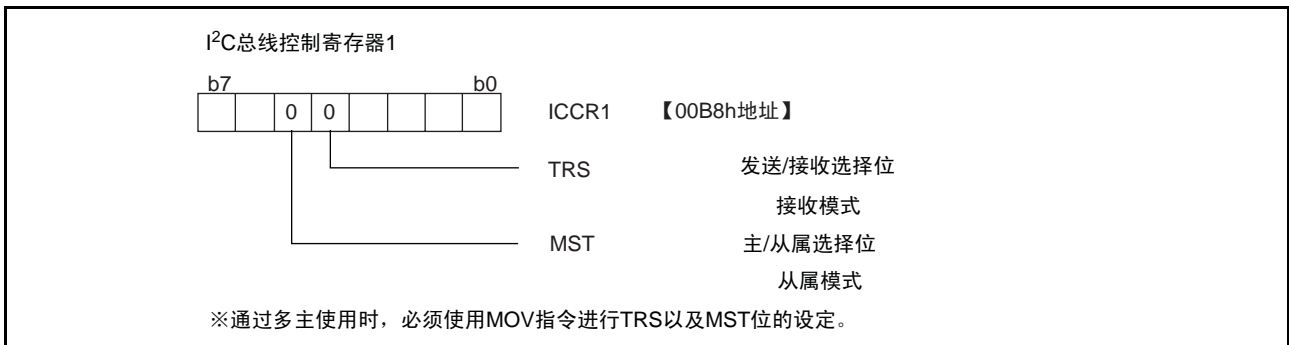
(12) 将ICSR寄存器的STOP位清“0”。



(13) 将 ICIER 寄存器的 ACKBT 位设定为 “0”。



(14) 返回从属接收模式。



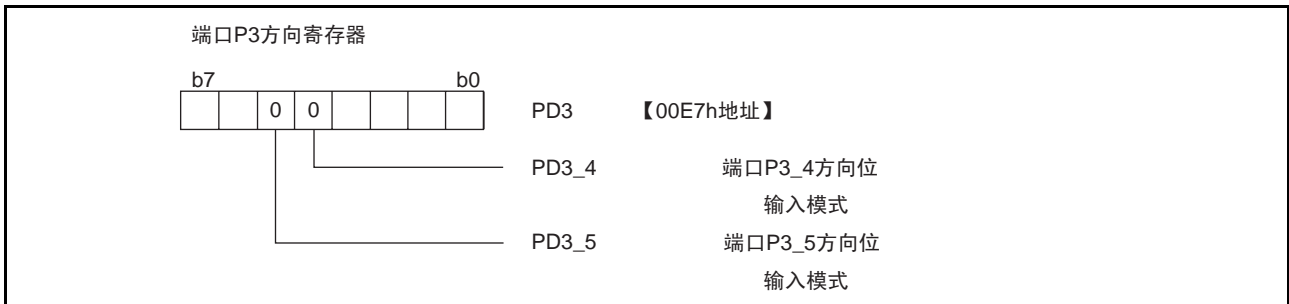
4.4 从属发送/接收模式的设定

4.4.1 初始设定

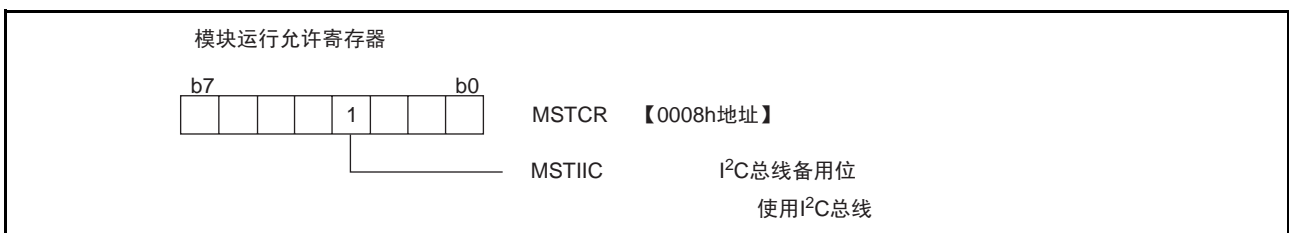
设定为可进行传送状态，并设定传送时钟和传送格式。

在此设定的时钟，用于发送模式时的数据设置。通信时钟从主器件输出。

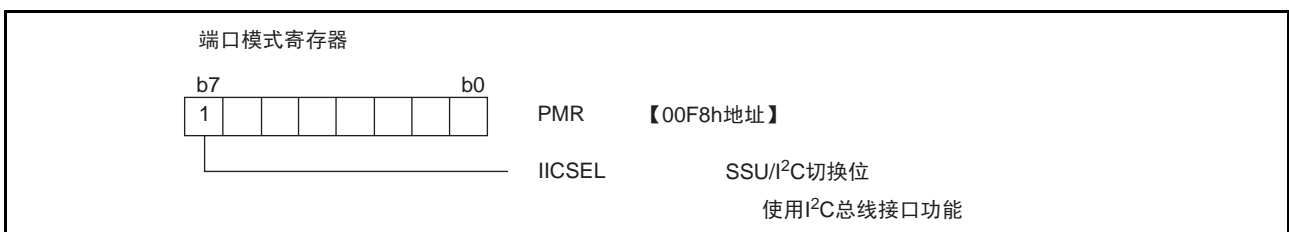
(1) 将端口P3_4方向位、端口P3_5方向位设定为输入模式。



(2) 设定I²C总线备用位。



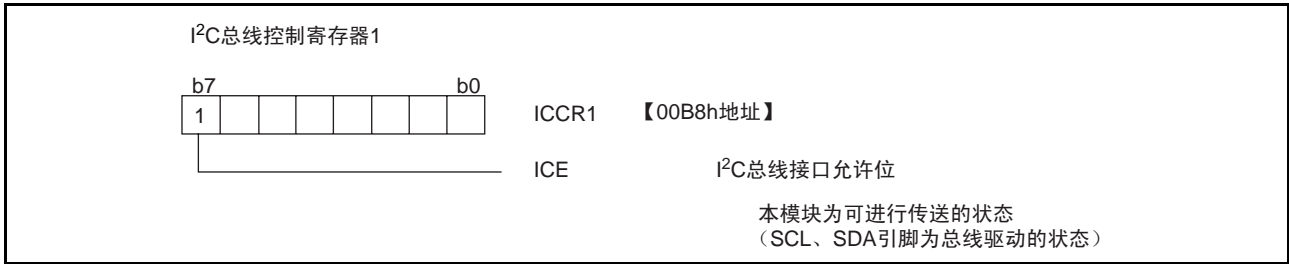
(3) 设定SSU/I²C切换位。



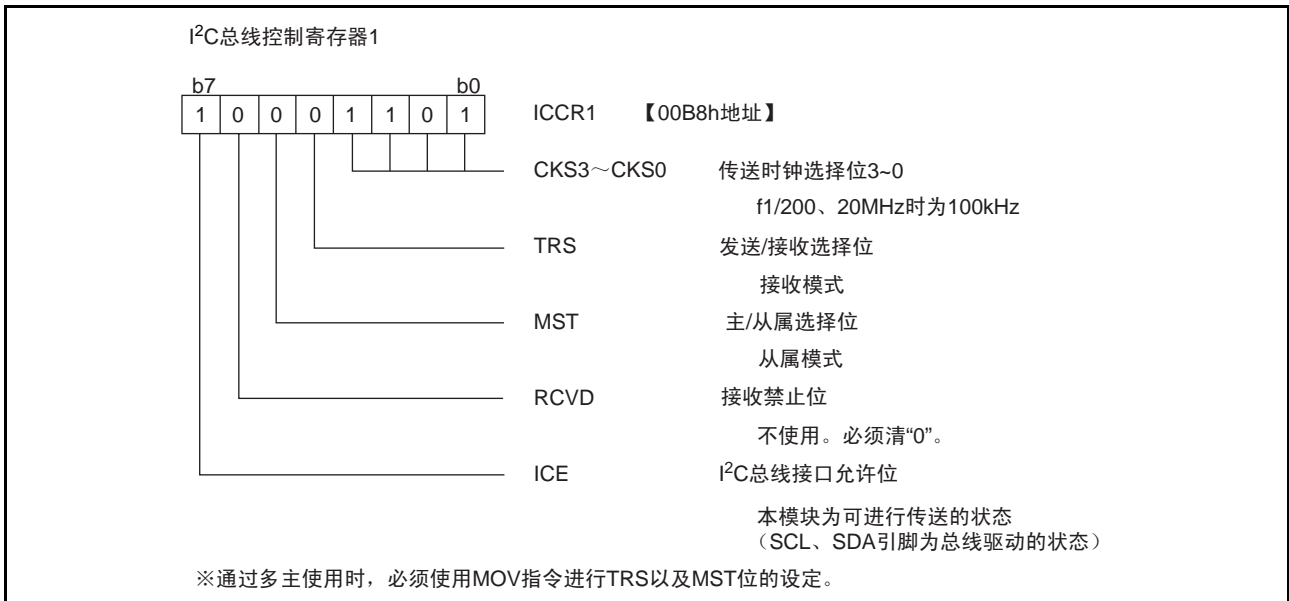
(4) 初始化ICSR寄存器的STOP位。



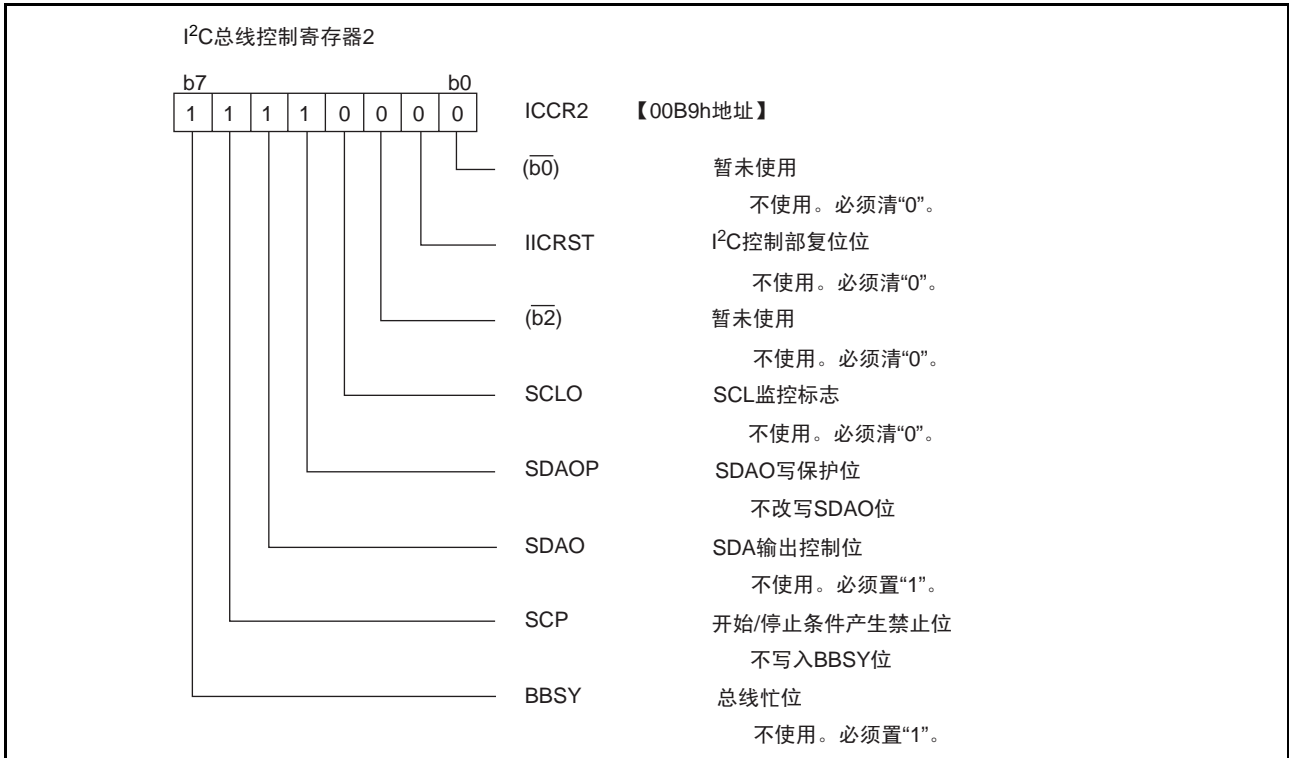
(5) 将I²C总线设定为可进行传送状态。



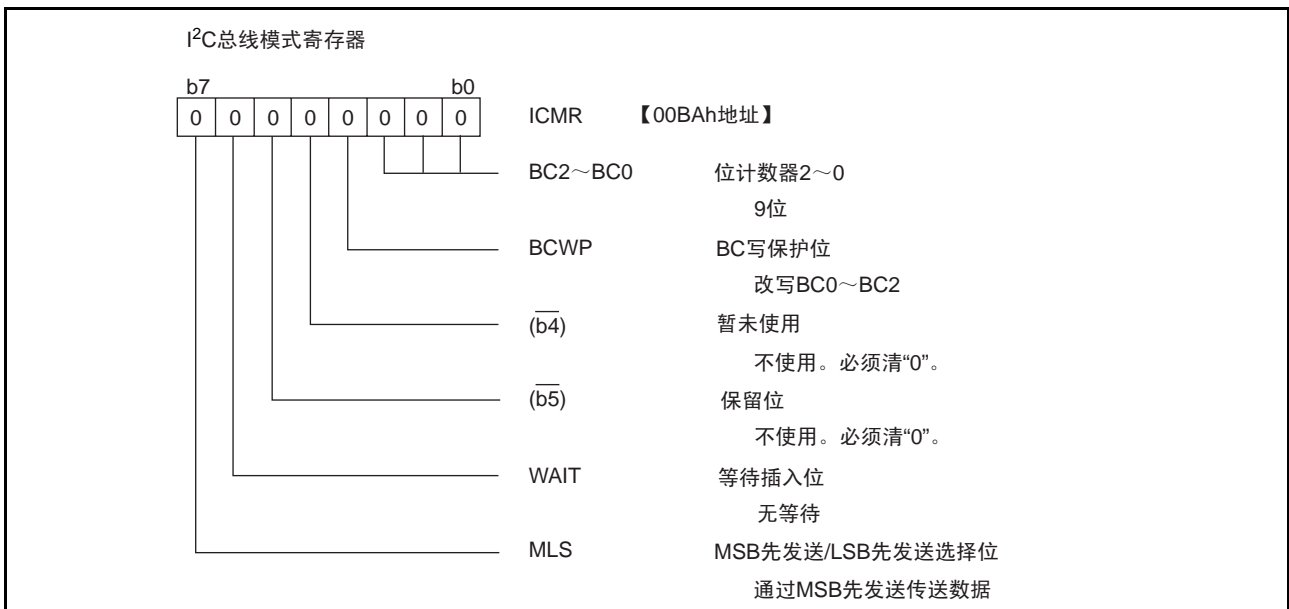
(6) 设定I²C总线控制寄存器1。



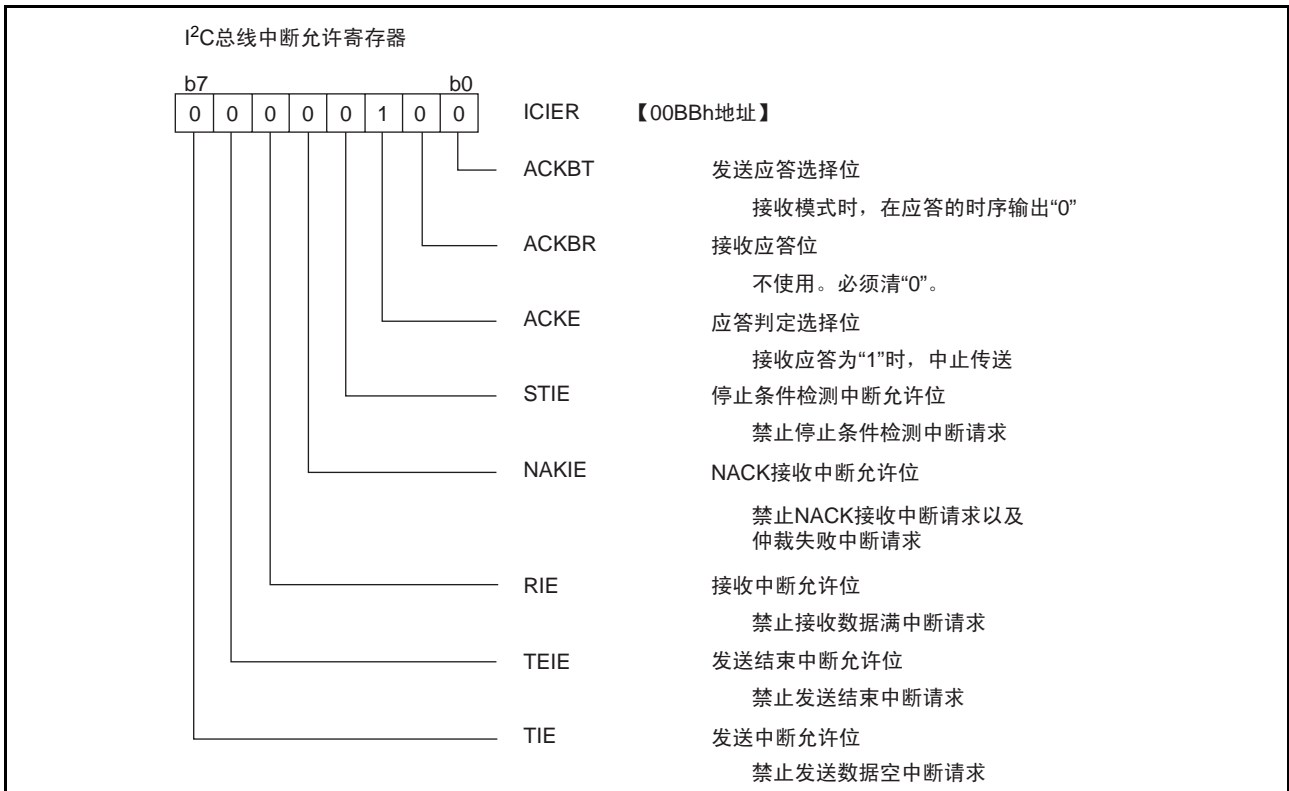
(7) 设定 I²C 总线控制寄存器 2。



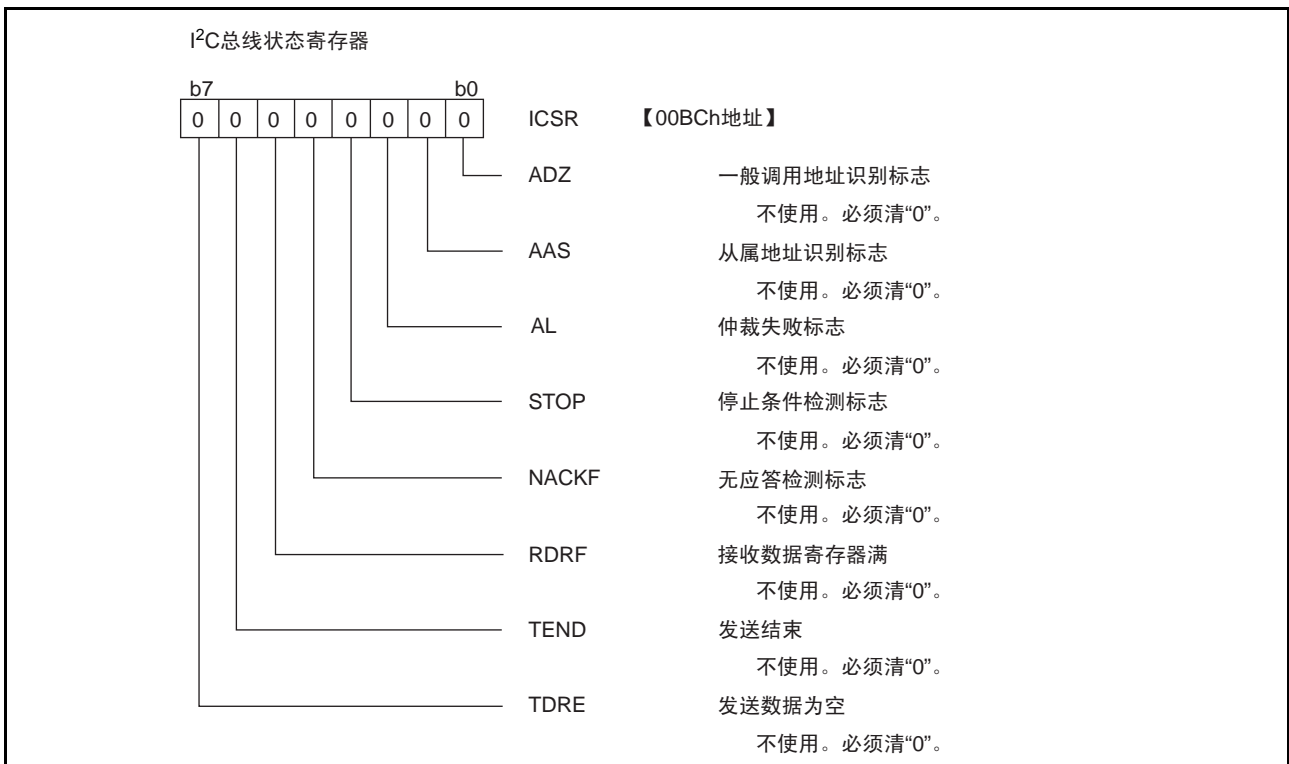
(8) 设定 I²C 总线模式寄存器。



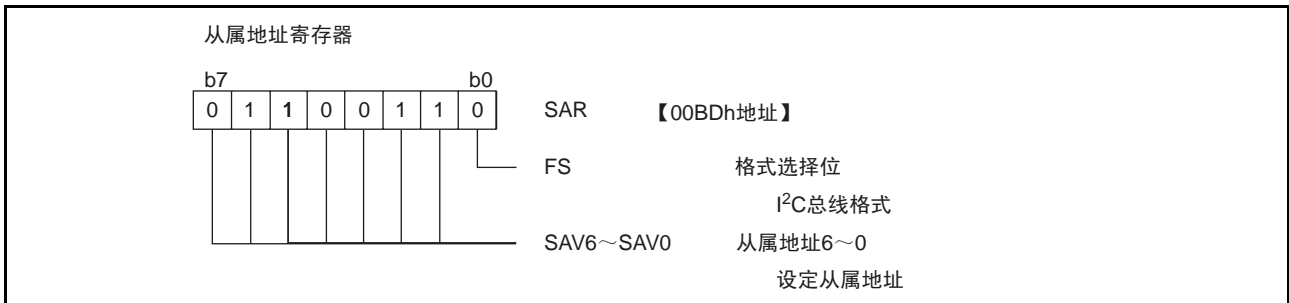
(9) 设定 I²C 总线中断允许寄存器。



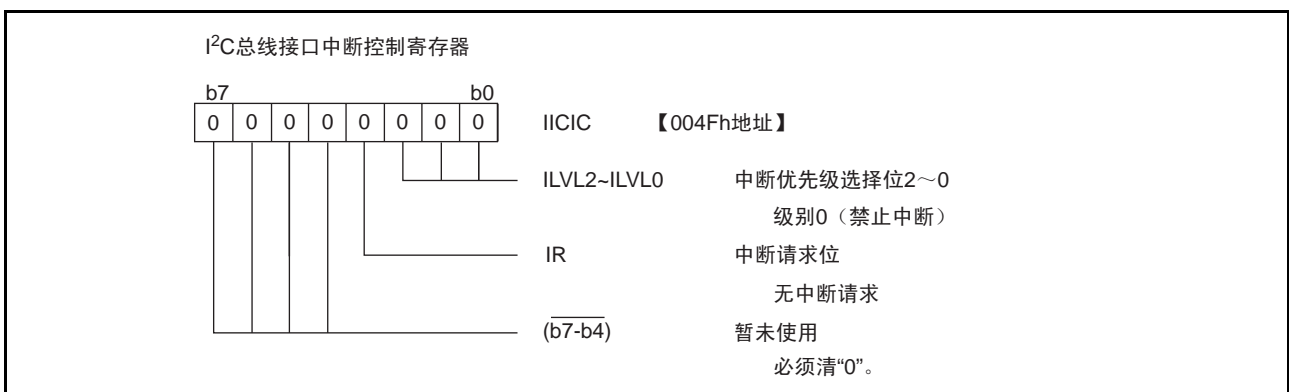
(10) 设定 I²C 总线状态寄存器。



(11) 设定从属地址寄存器。



(12) 设定I²C总线接口中断控制寄存器。



4.4.2 从属发送

(1) 在从属模式下读ICSR寄存器的AAS位，直到从属地址匹配为止。

(2) 在检测开始条件后的第1帧时，如果出现从属地址匹配，从属器件在第9个时钟的上升沿向SDA输出在ICIER寄存器的ACKBT位设定的电平。此时，第8位的数据数据（R/W）为“1”时，TRS位以及ICSR寄存器的TDRE位变为“1”，并自动转换为从属发送模式。

(3) 初始化ICSR寄存器的STOP位。

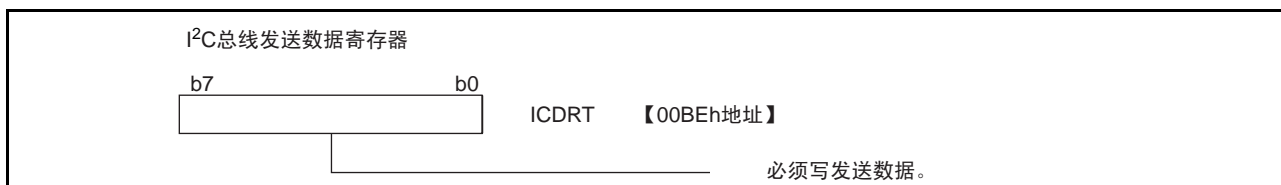


(4) 虚读ICDRR寄存器（因为读出的数据显示为从属地址+R/W，所以不需要）。

(5) 将ICSR寄存器的AAS位清“0”。



(6) 每当TDRE位变为“1”时，如果向ICDRT寄存器写发送数据就能够连续发送。



(7) 向ICDRT寄存器内写最终发送数据后TDRE位变为“1”时，在TDRE位为“1”的状态下等待ICSR寄存器的TEND位变为“1”。如果TEND位变为“1”，必须将TEND位清“0”。

(8) 将 ICSR 寄存器的 NACKF 位清 “0”。



(9) 将 ICCR1 寄存器的 TRS 位设定为接收模式。



(10) 必须虚读 ICDRR 寄存器。由此开放 SCL。

(11) 必须通过读 ICSR 寄存器的 STOP 位，确认已检测到停止条件。

(12) 将 ICSR 寄存器的 STOP 位清 “0”。



4.4.3 接收时

(1) 通过在从属接收模式下读 ICSR 寄存器的 AAS 位，直到从属地址匹配为止。

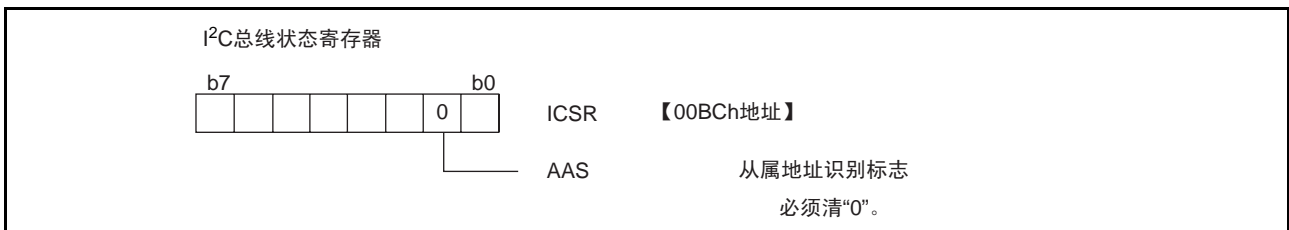
(2) 在检测开始条件后的第 1 帧时，如果出现从属地址匹配，从属器件在第 9 个时钟的上升沿向 SDA 输出在 ICIER 寄存器的 ACKBT 位设定的电平。

(3) 初始化 ICSR 寄存器的 STOP 位。

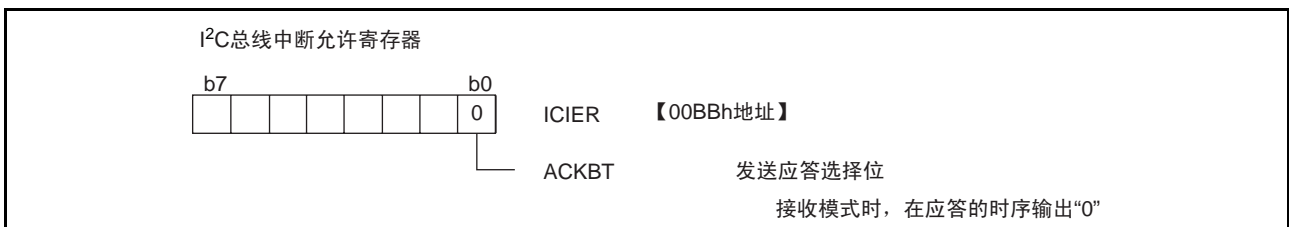


(4) 必须虚读 ICDRR 寄存器（因为读出的数据显示为从属地址 + R/W，所以不需要）。

(5) 将 ICSR 寄存器的 AAS 位清 “0”。



(6) 将 ICIER 寄存器的 ACKBT 位设定为 “0”。



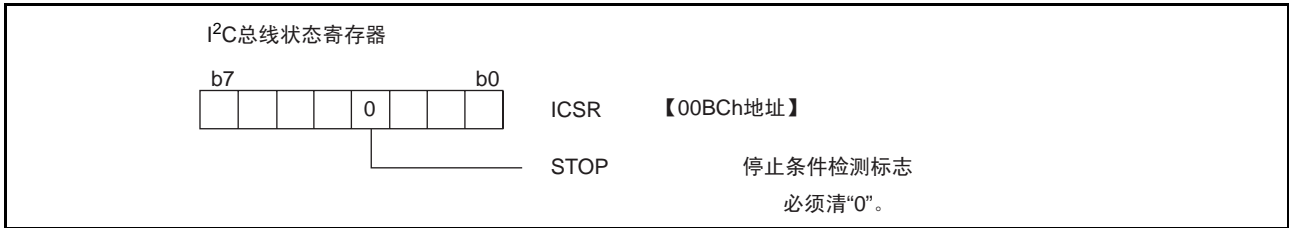
(7) 必须虚读 ICDRR 寄存器。

(8) 每当 RDRF 位变为 “1” 时，必须读 ICDRR 寄存器。在 RDRF 位为 “1” 的状态下，如果第 8 个时钟下降，就将 SCL 固定为 “L” 直到读 ICDRR 寄存器为止。在读 ICDRR 寄存器之前进行的返回主器件的应答的设置变更在下一次的传送帧显示。

(9) 最终字节的读出也同样通过读 ICDRR 寄存器来进行。

(10) 必须通过读 ICSR 寄存器的 STOP 位，确认已检测到停止条件。

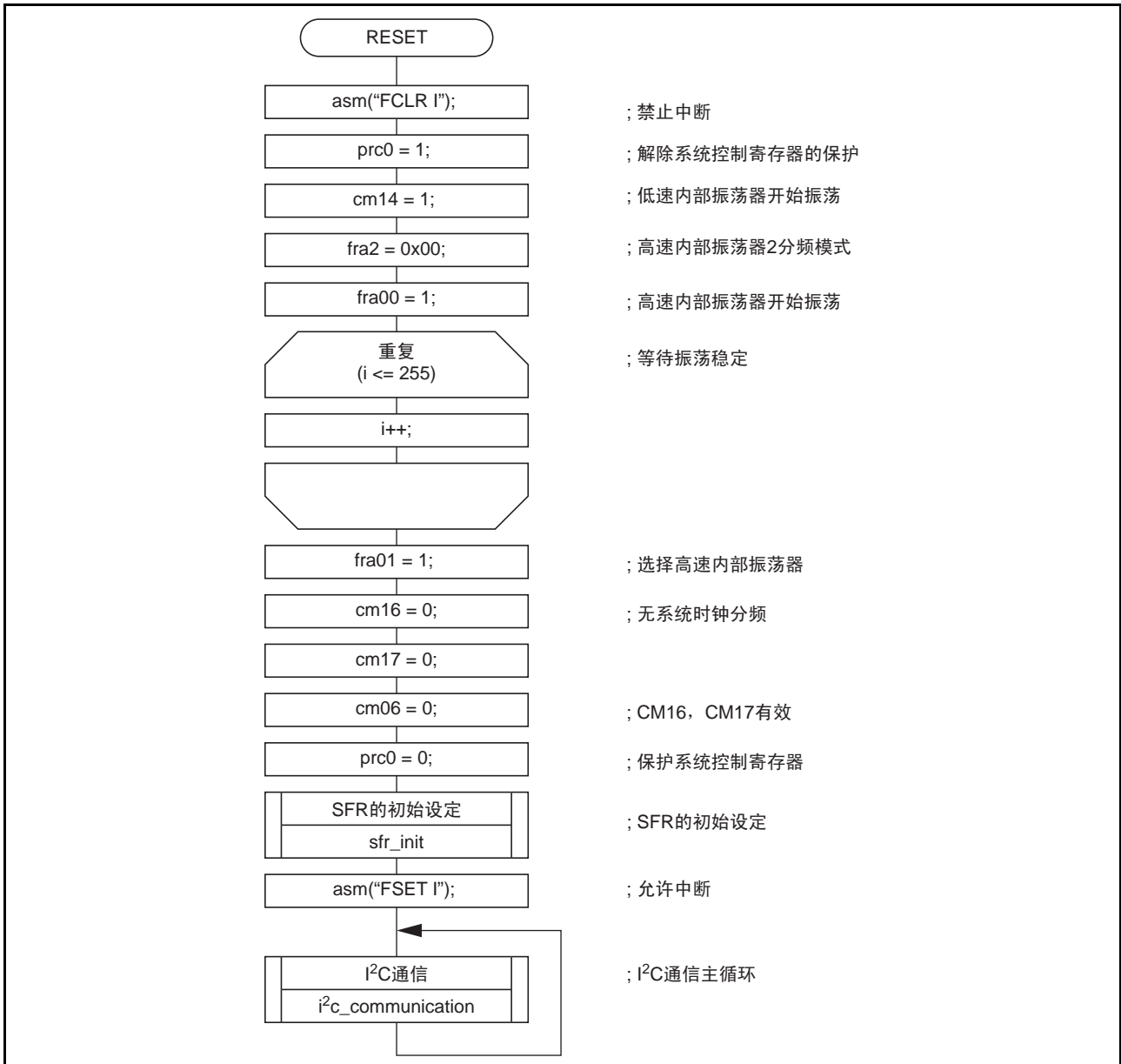
(11) 将 ICSR 寄存器的 STOP 位清 “0”。



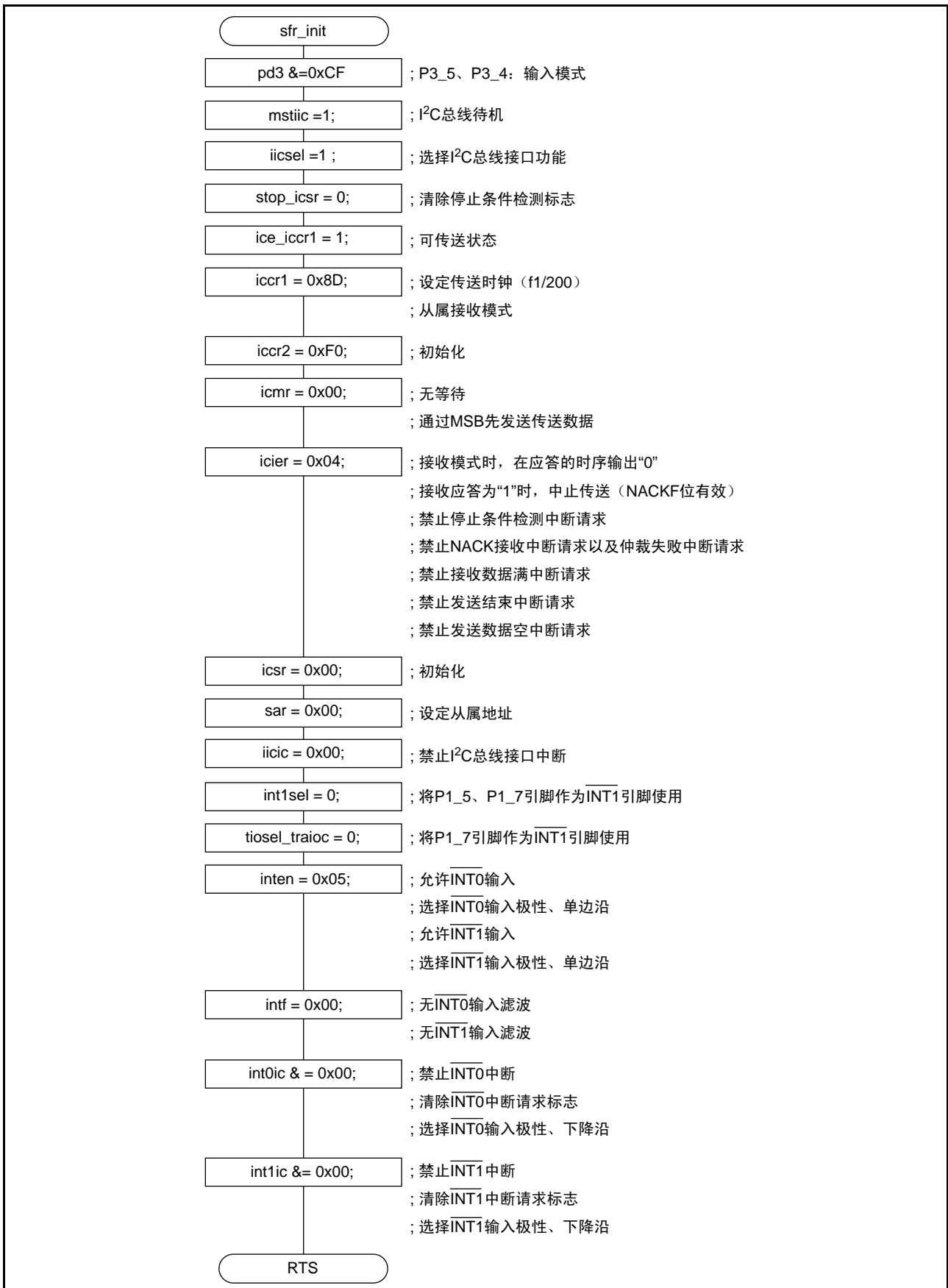
5. 流程图

5.1 主发送/接收模式（单主时）

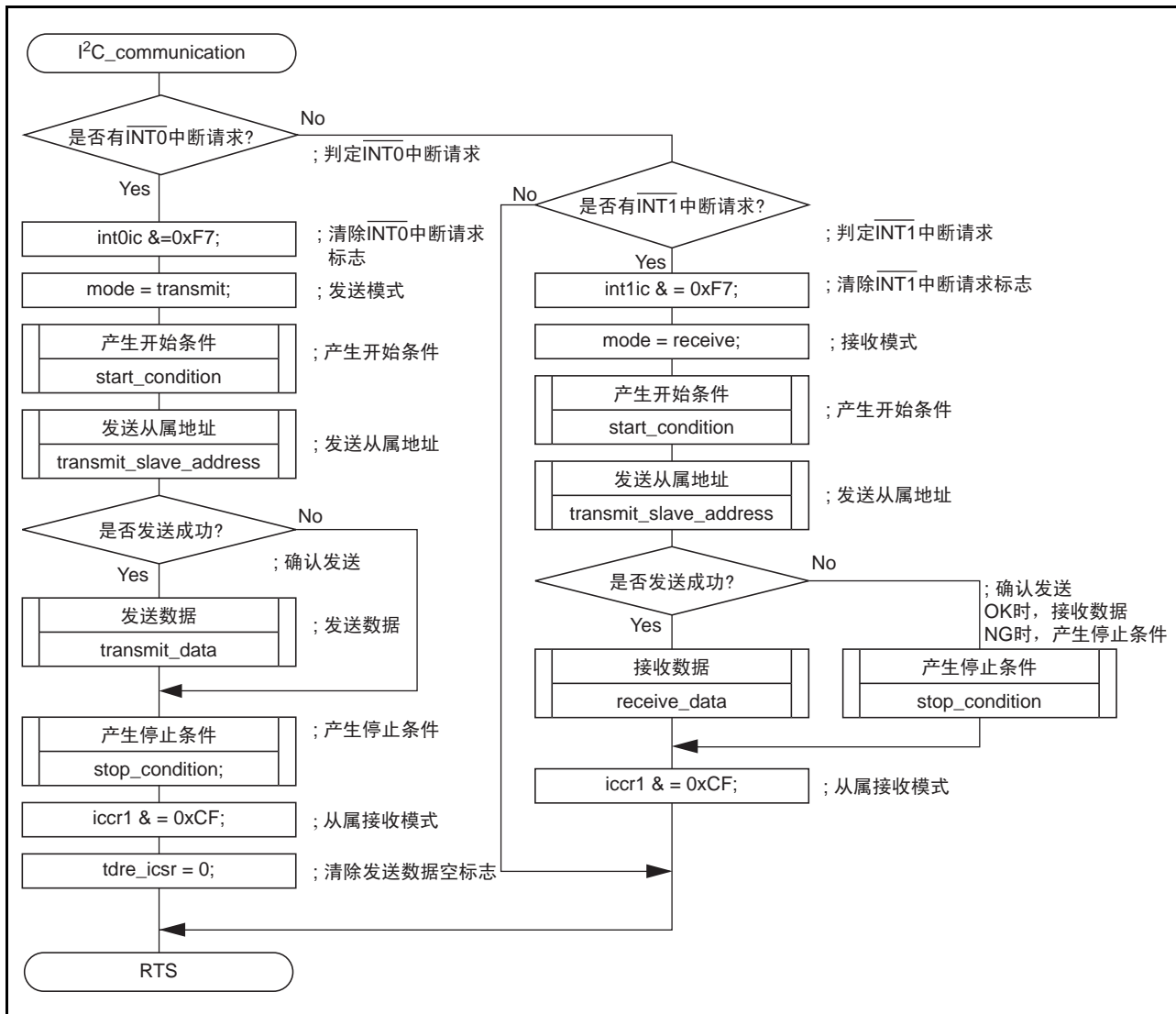
5.1.1 初始设定和主循环



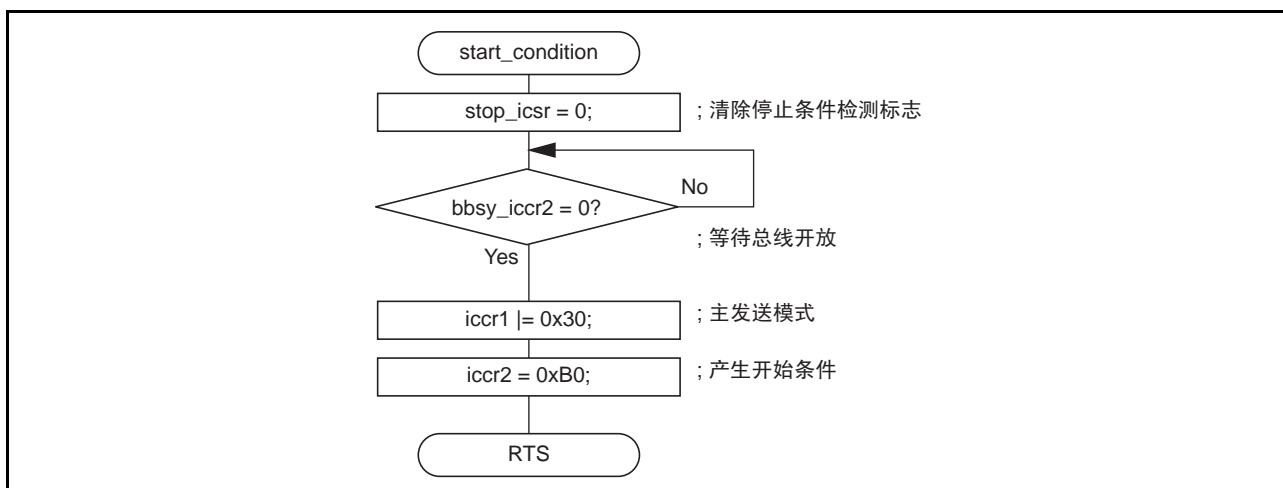
5.1.2 SFR的初始设定



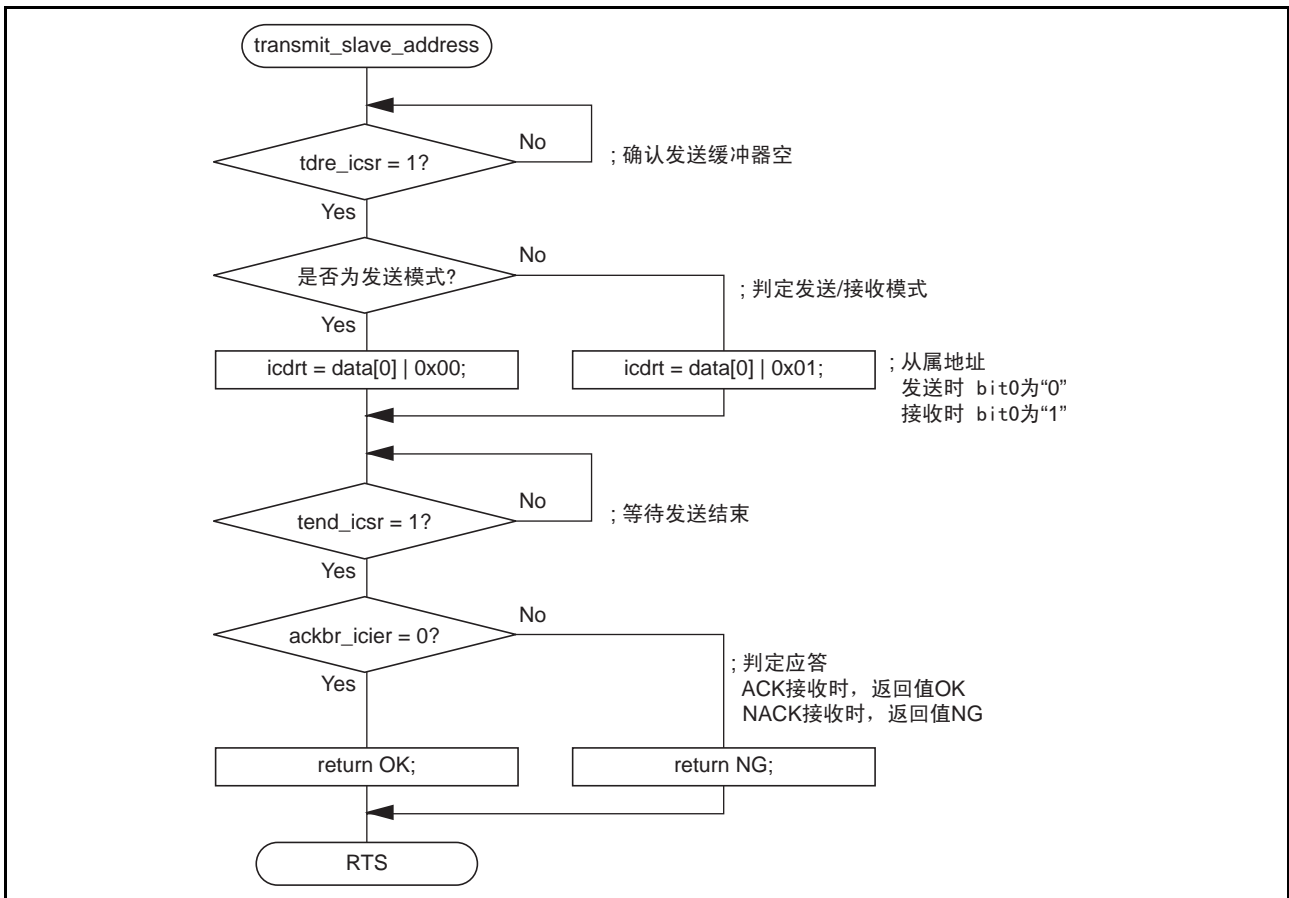
5.1.3 I²C通信主循环



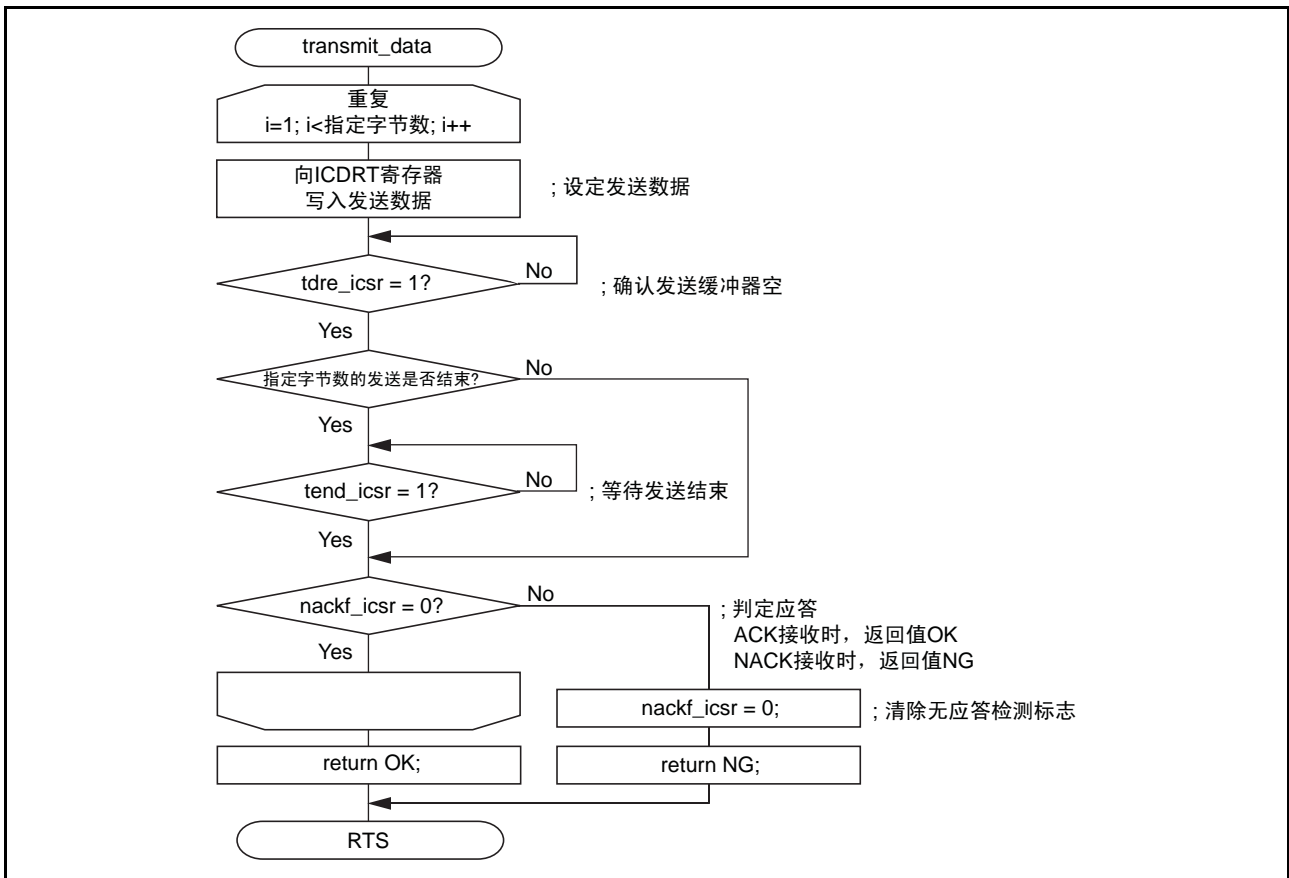
5.1.4 开始条件的产生



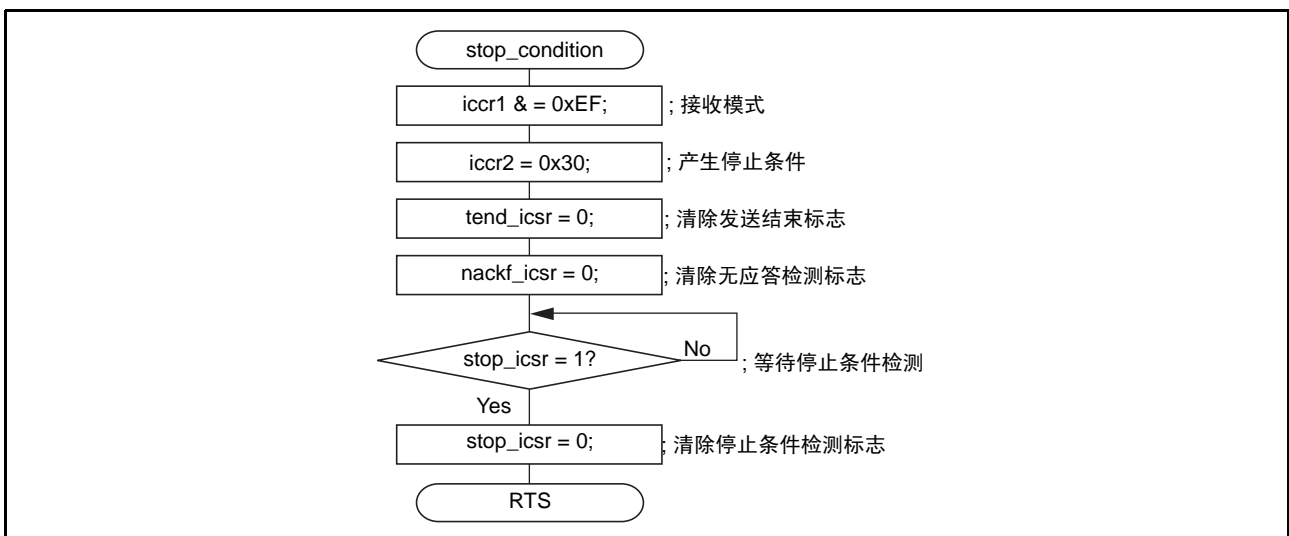
5.1.5 从属地址的发送



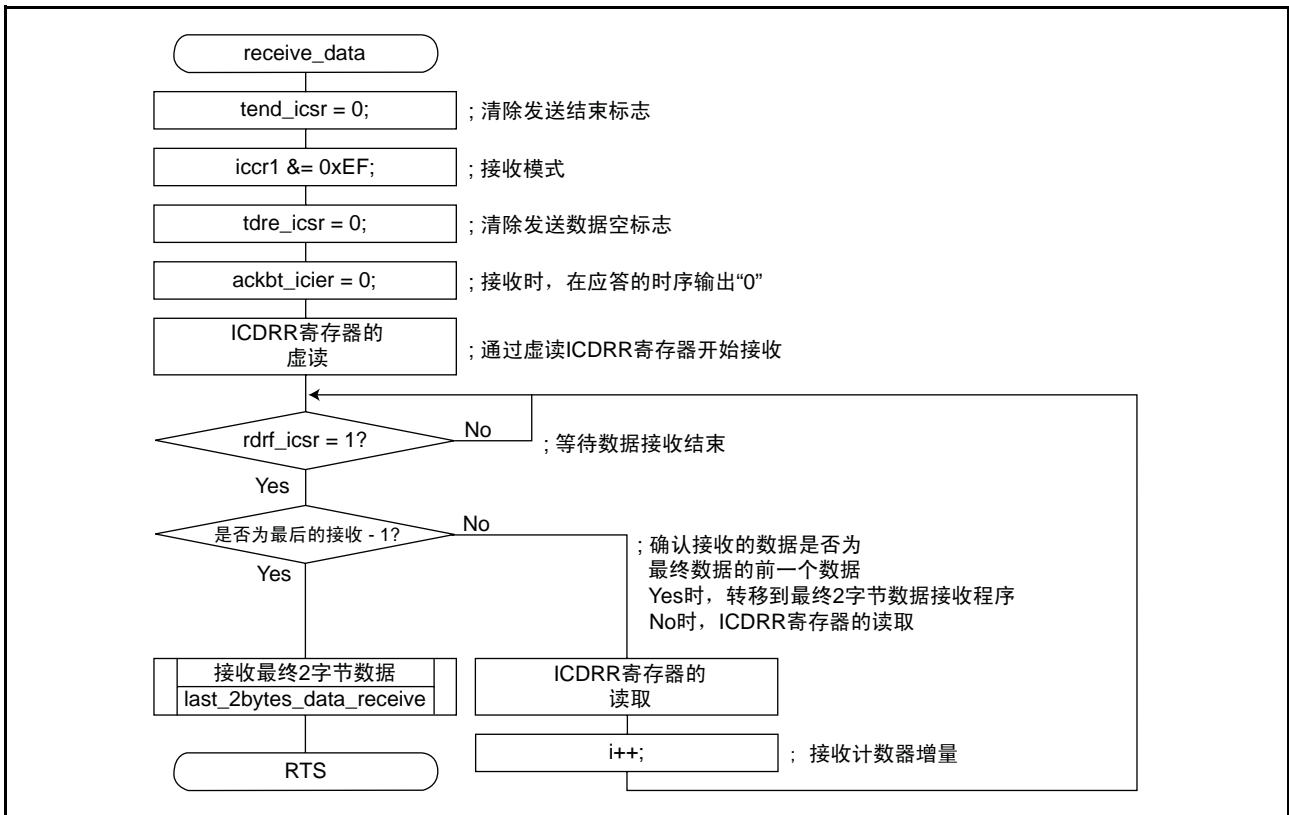
5.1.6 数据的发送



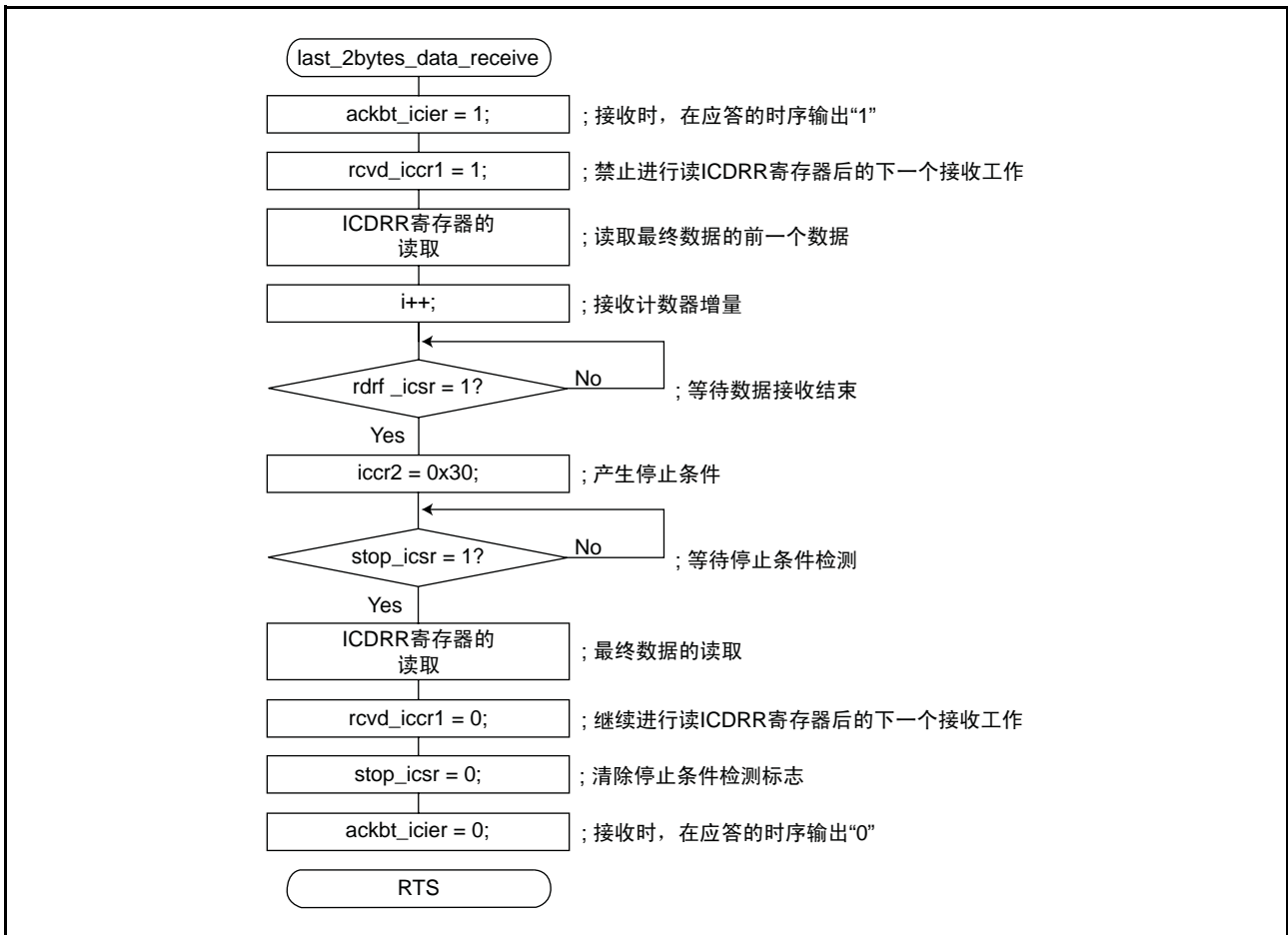
5.1.7 停止条件的产生



5.1.8 数据的接收

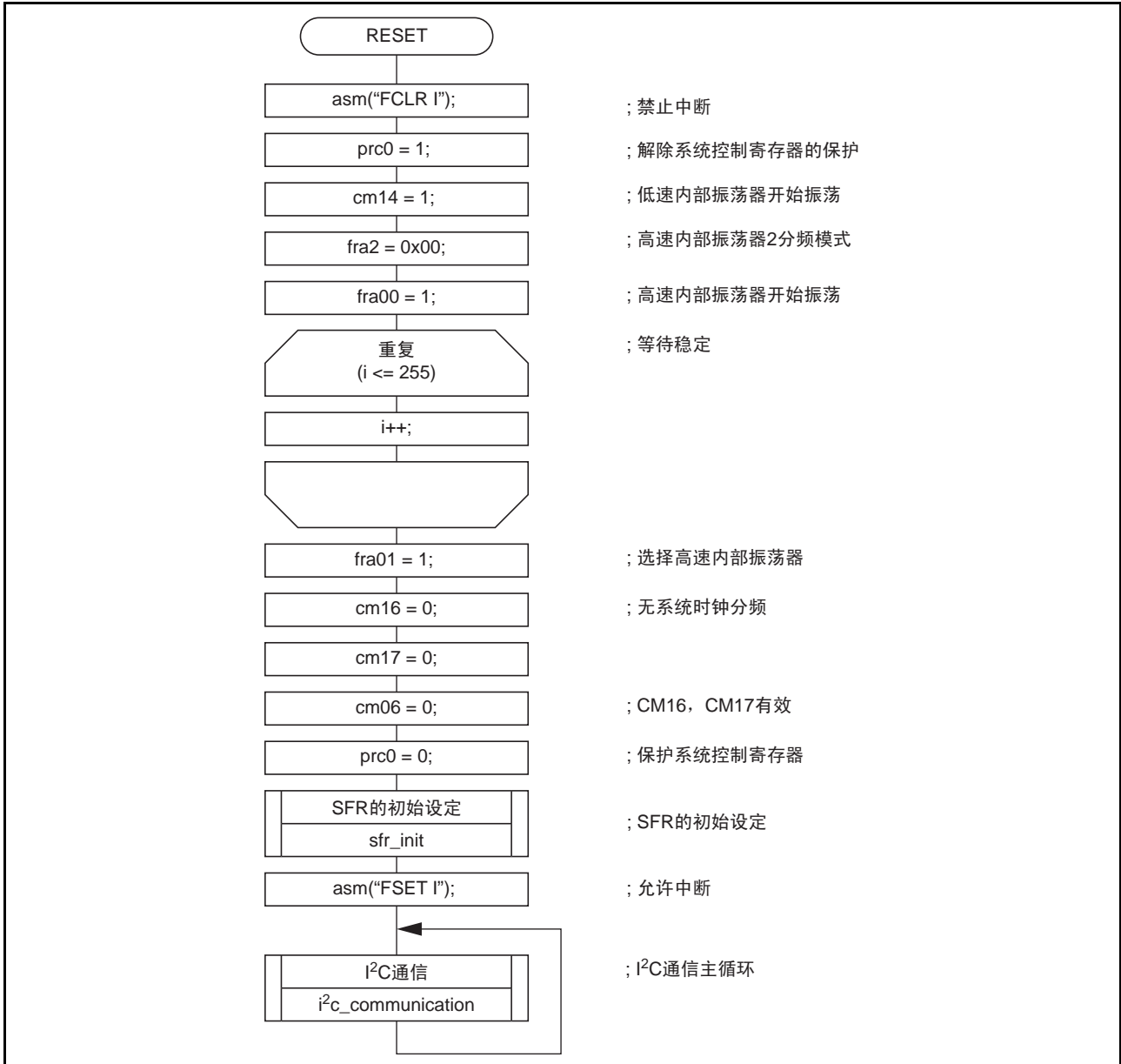


5.1.9 最终2字节数据的接收

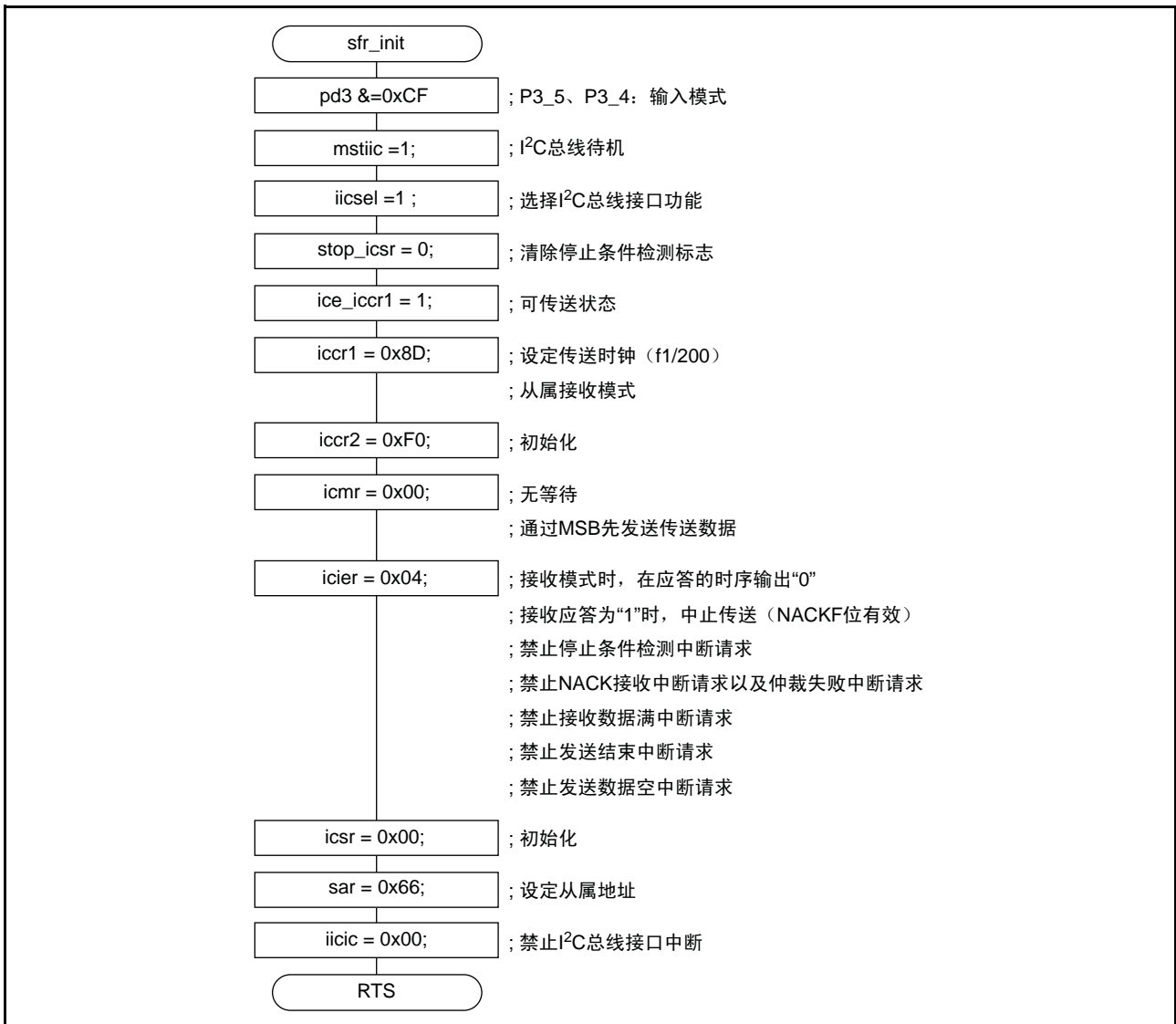


5.2 从属发送/接收模式

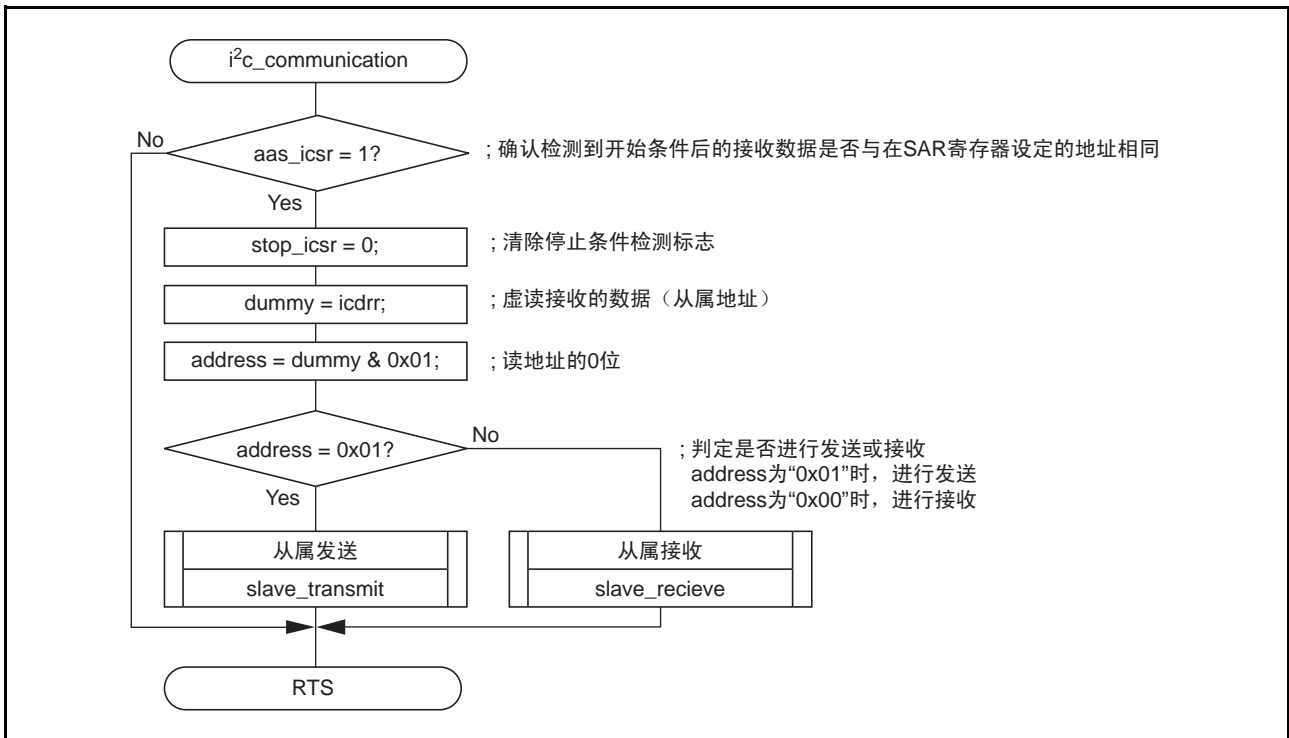
5.2.1 初始设定和主循环



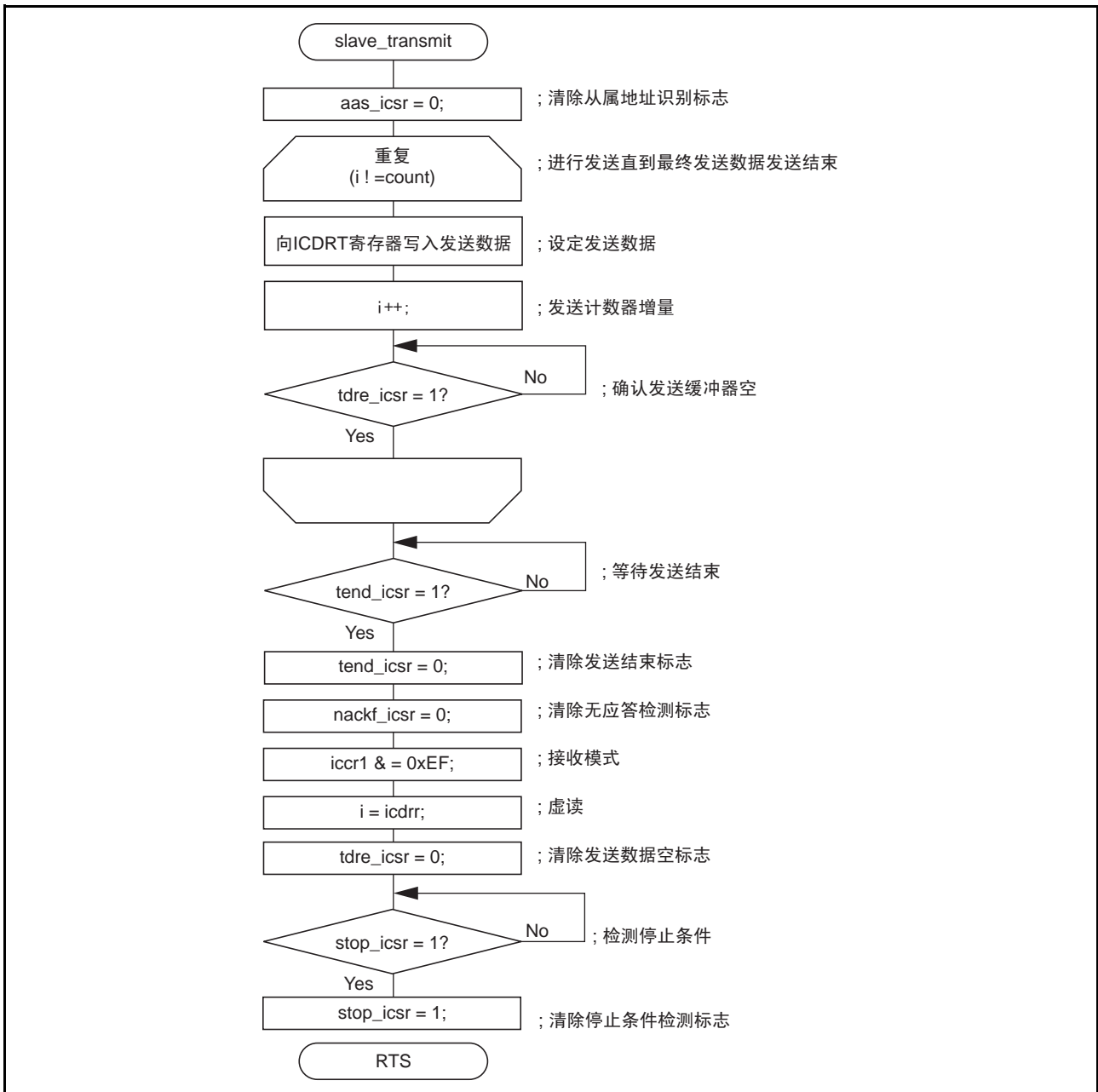
5.2.2 SFR的初始设定



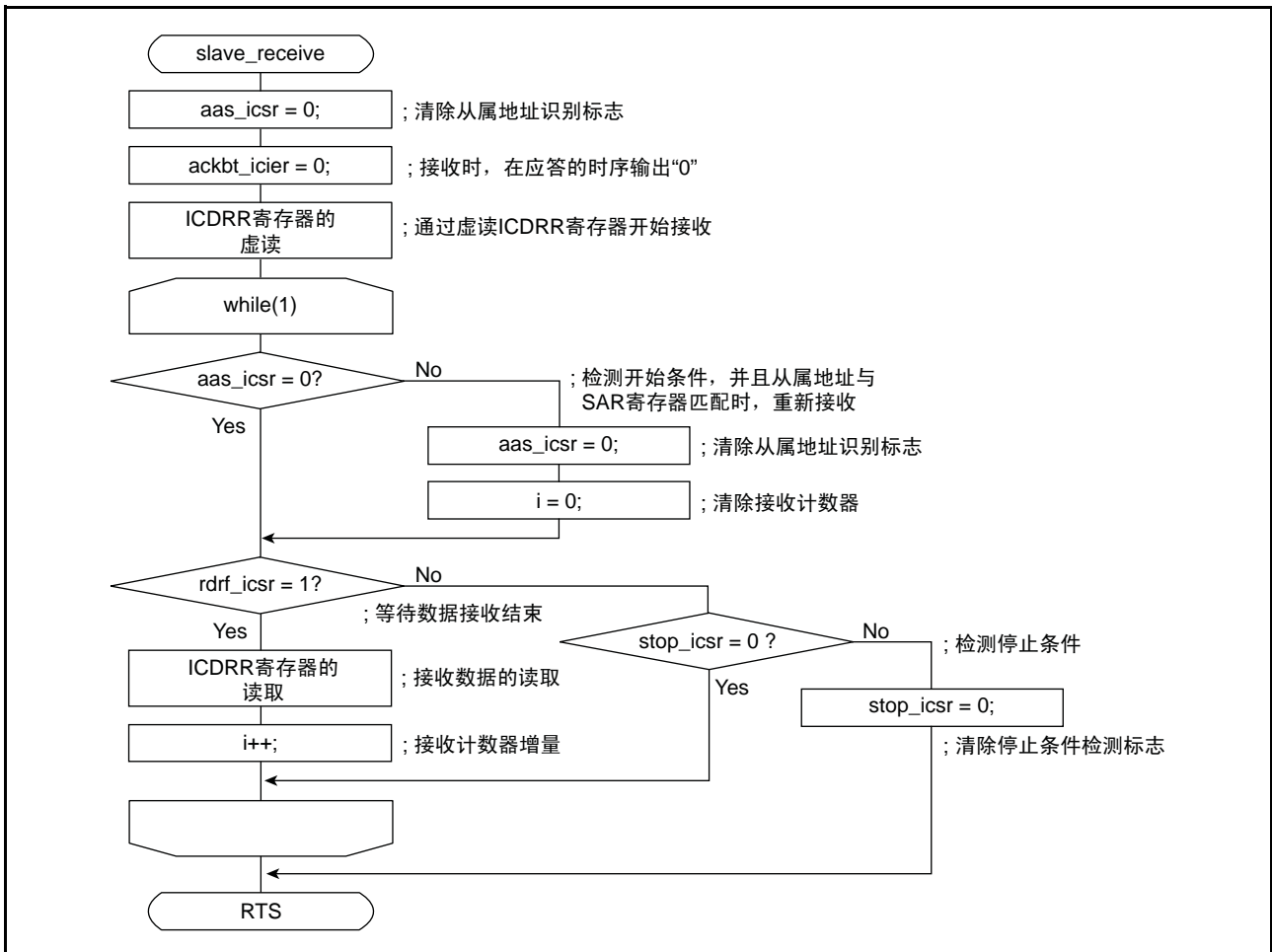
5.2.3 I²C通信主循环



5.2.4 从属发送

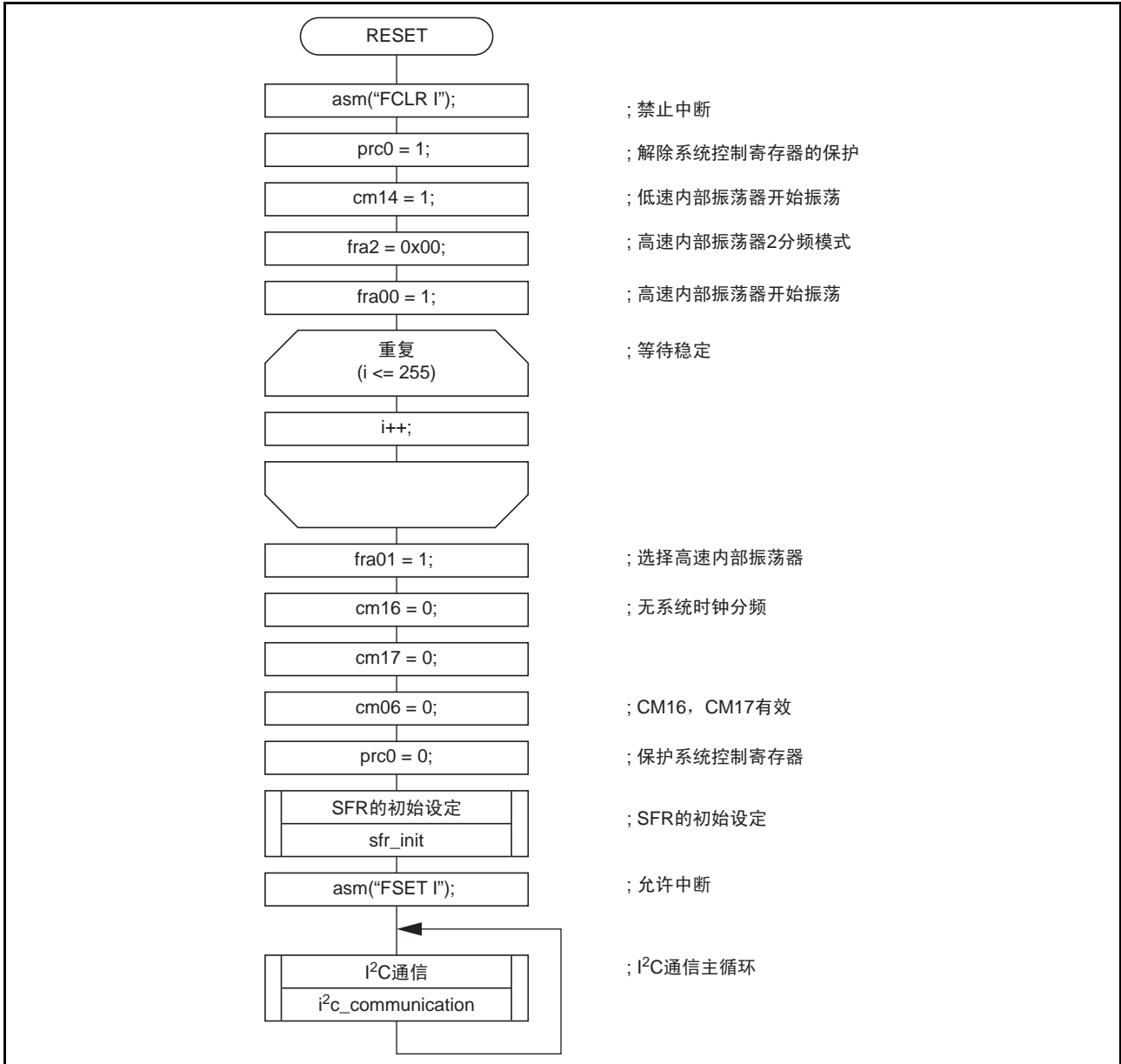


5.2.5 从属接收

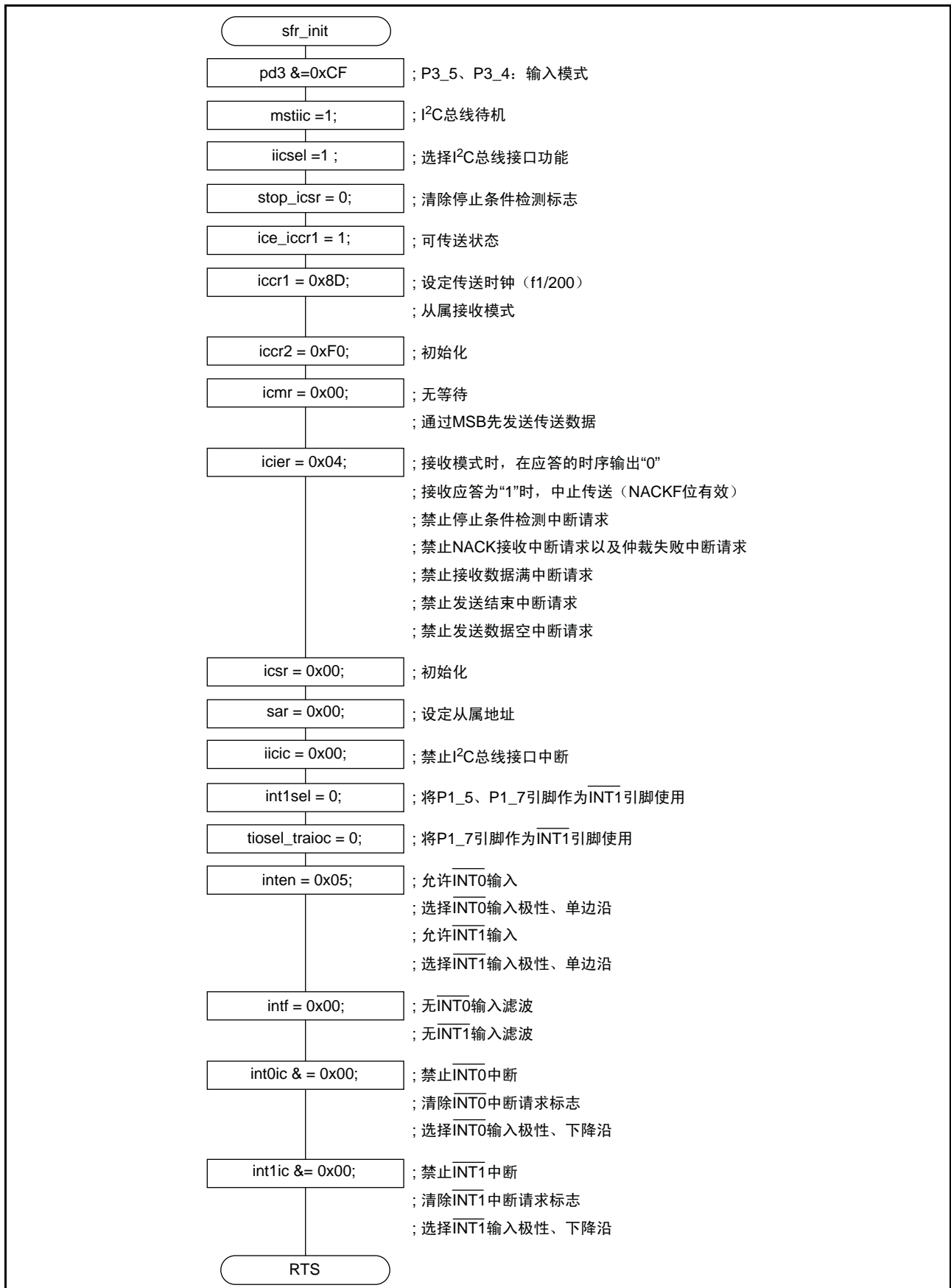


5.3 主发送/接收模式和从属发送/接收模式（多主时）

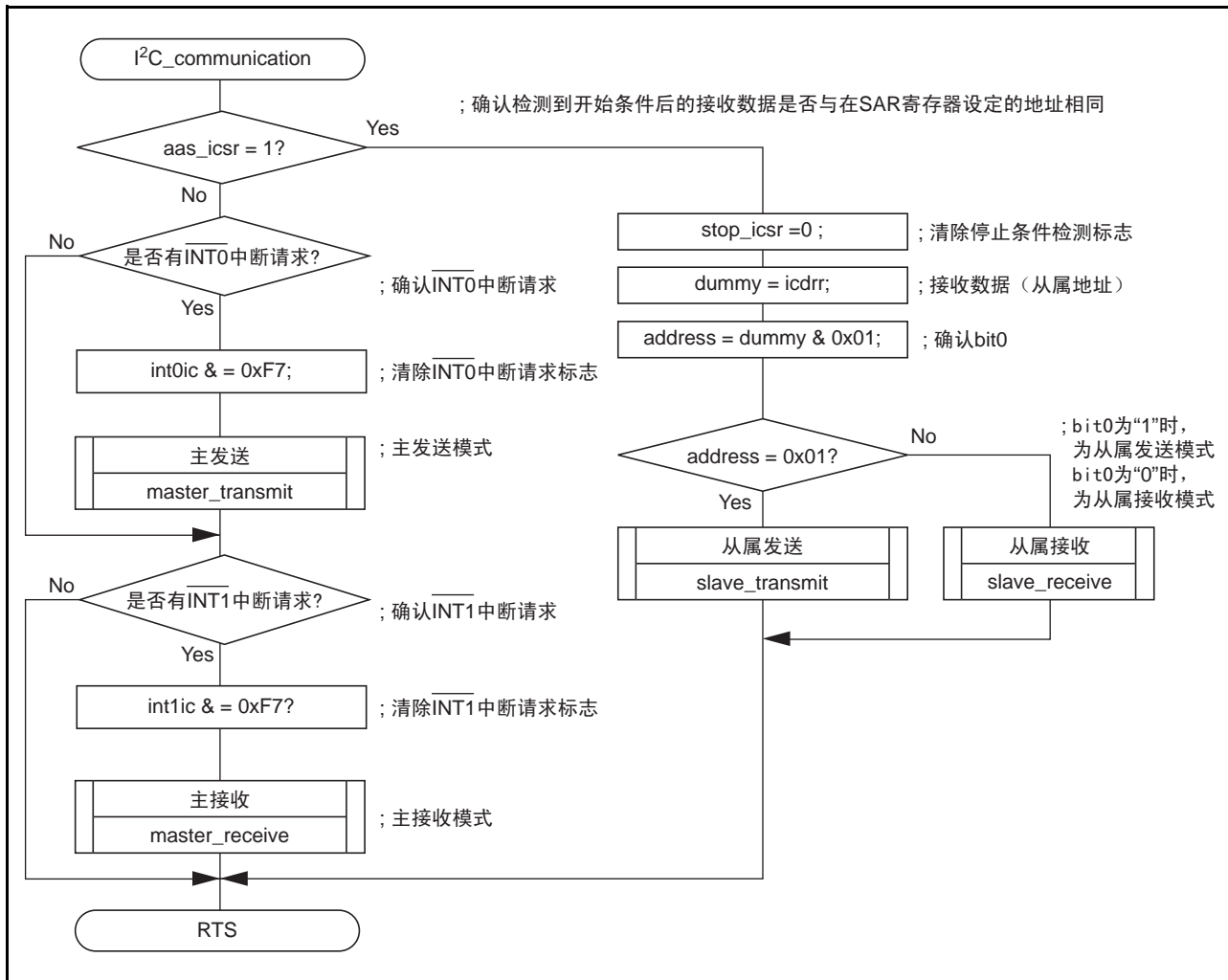
5.3.1 初始设定和主循环



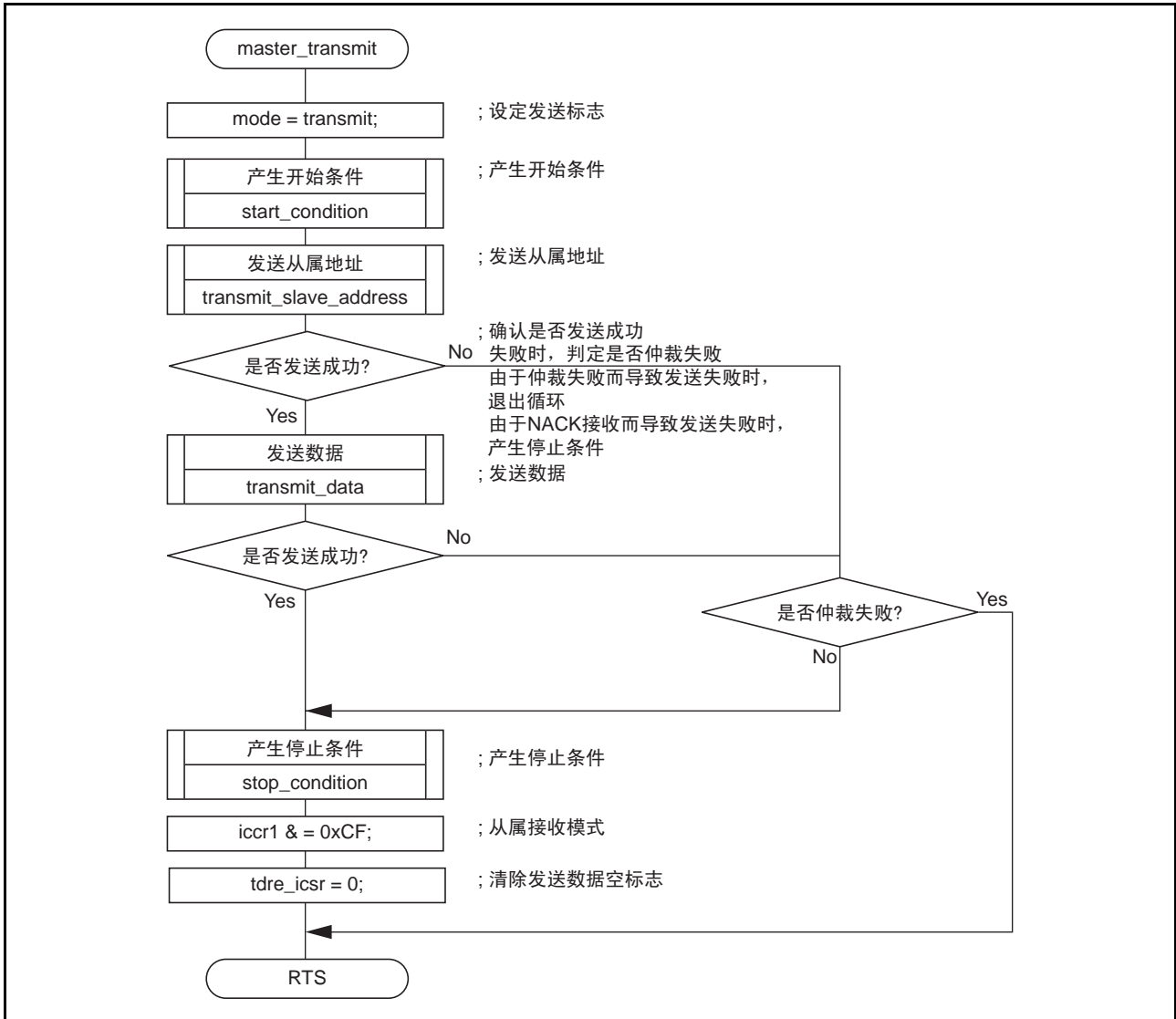
5.3.2 SFR的初始设定



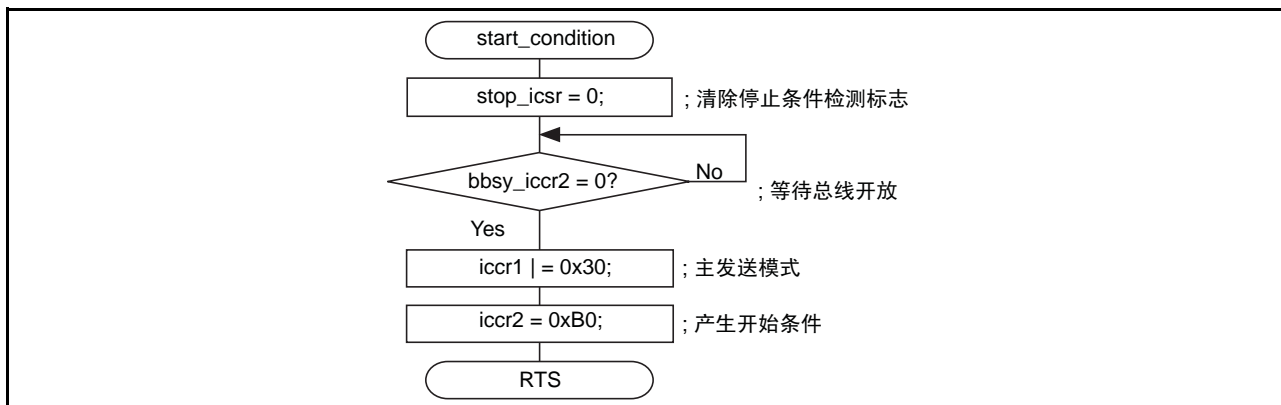
5.3.3 I²C通信主循环



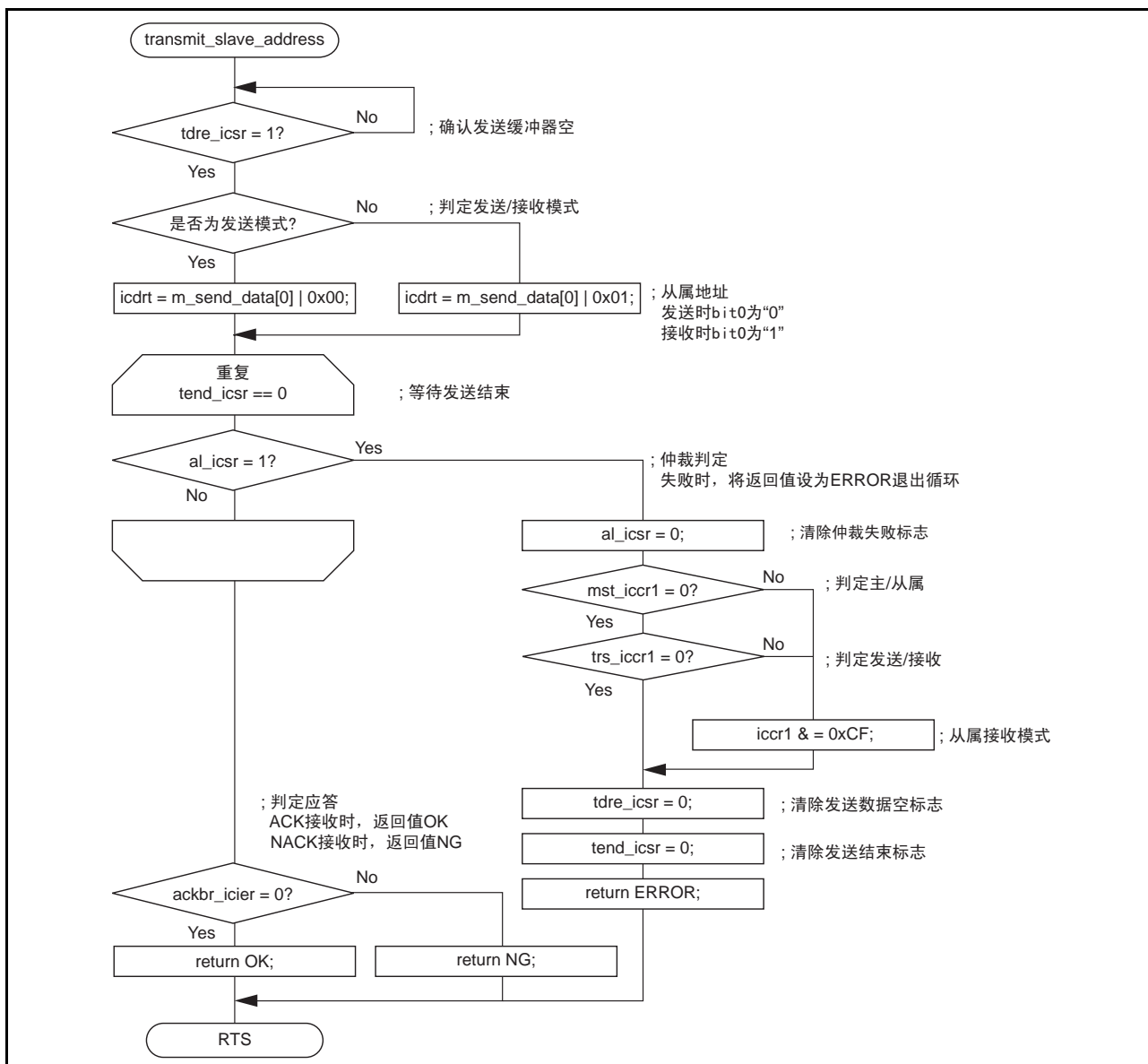
5.3.4 主发送



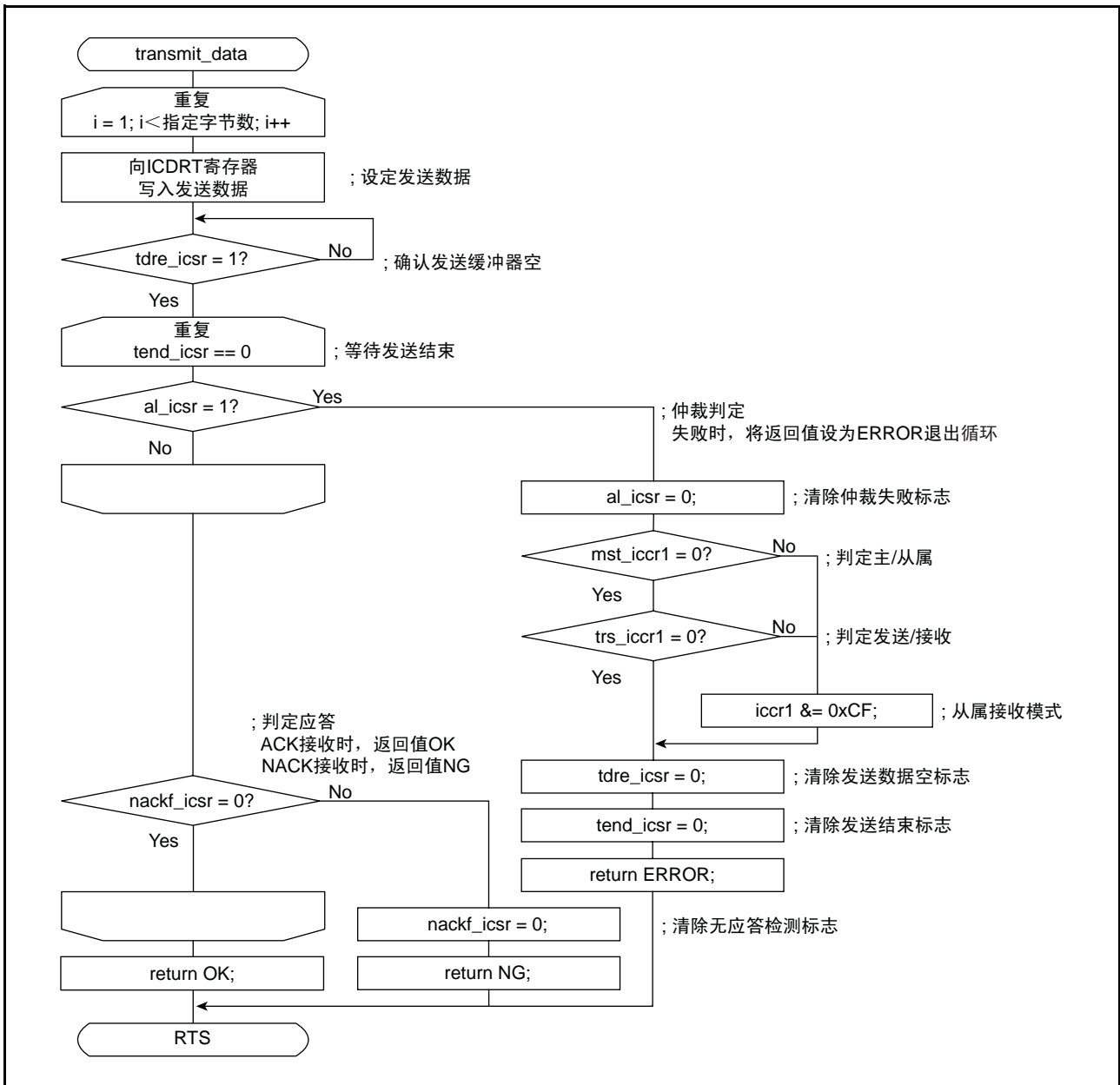
5.3.5 开始条件的产生



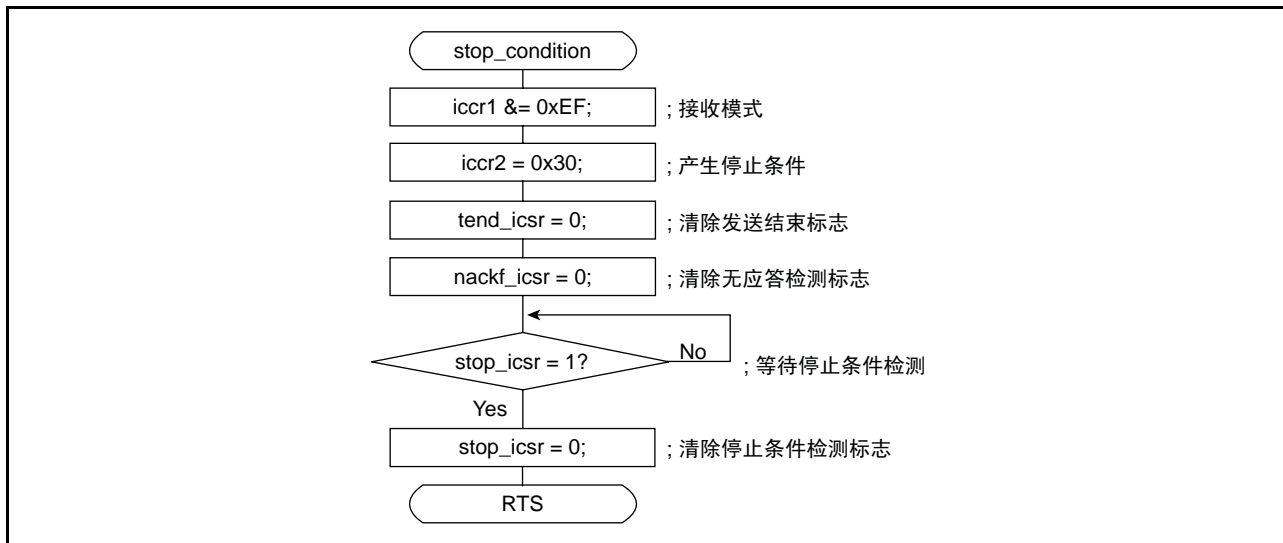
5.3.6 从属地址的发送



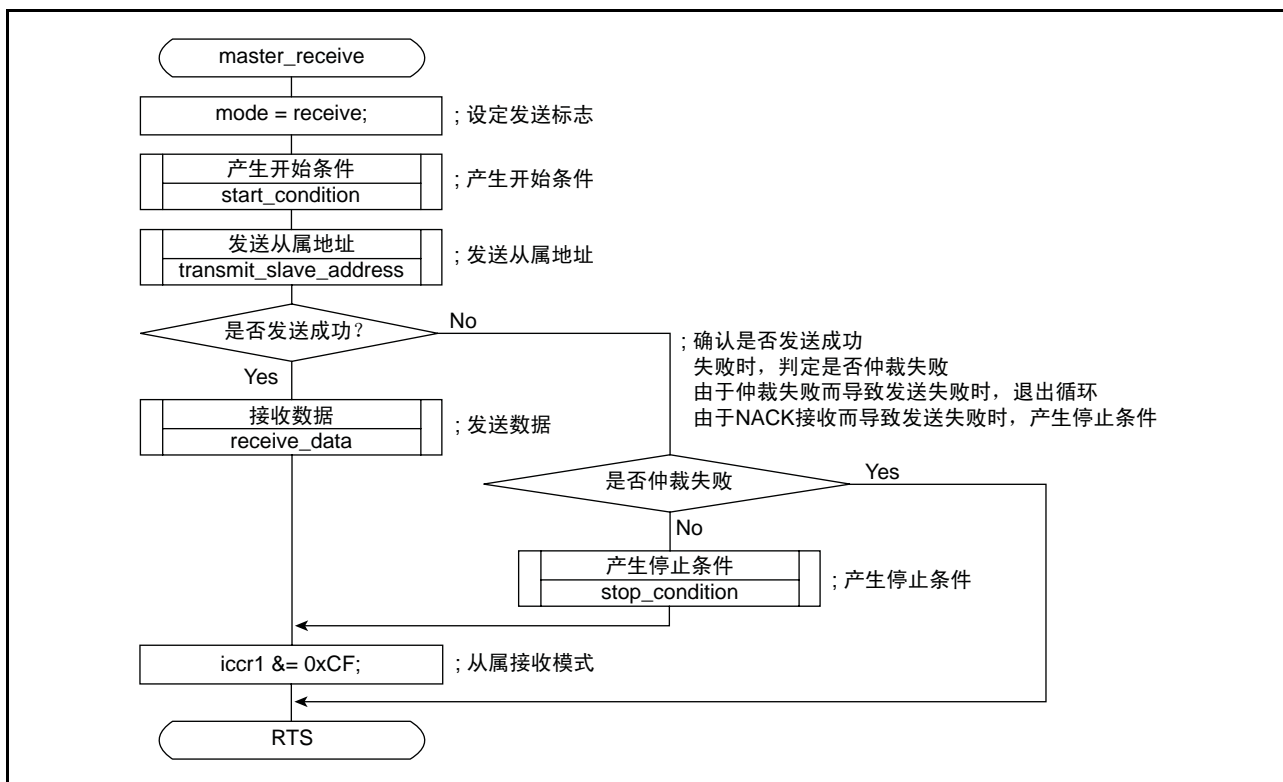
5.3.7 数据的发送



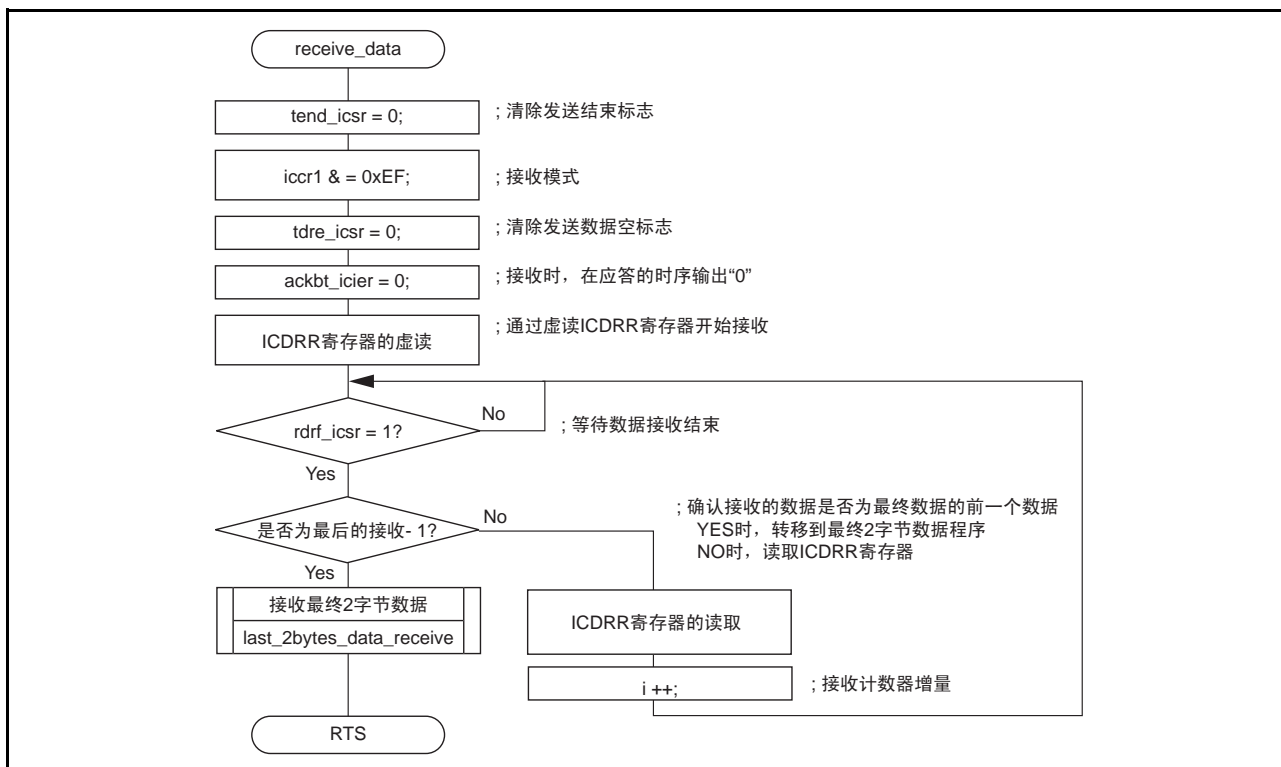
5.3.8 停止条件的产生



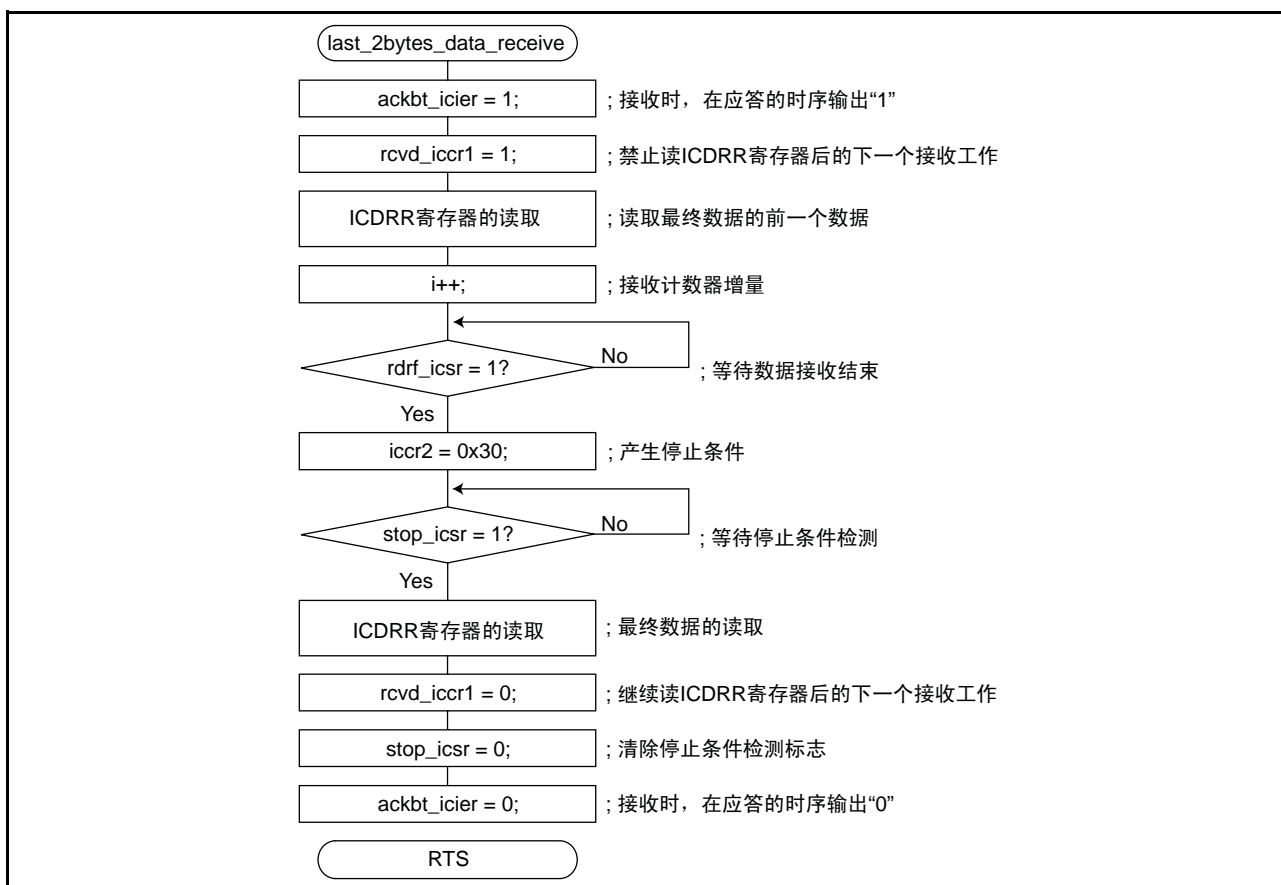
5.3.9 主接收



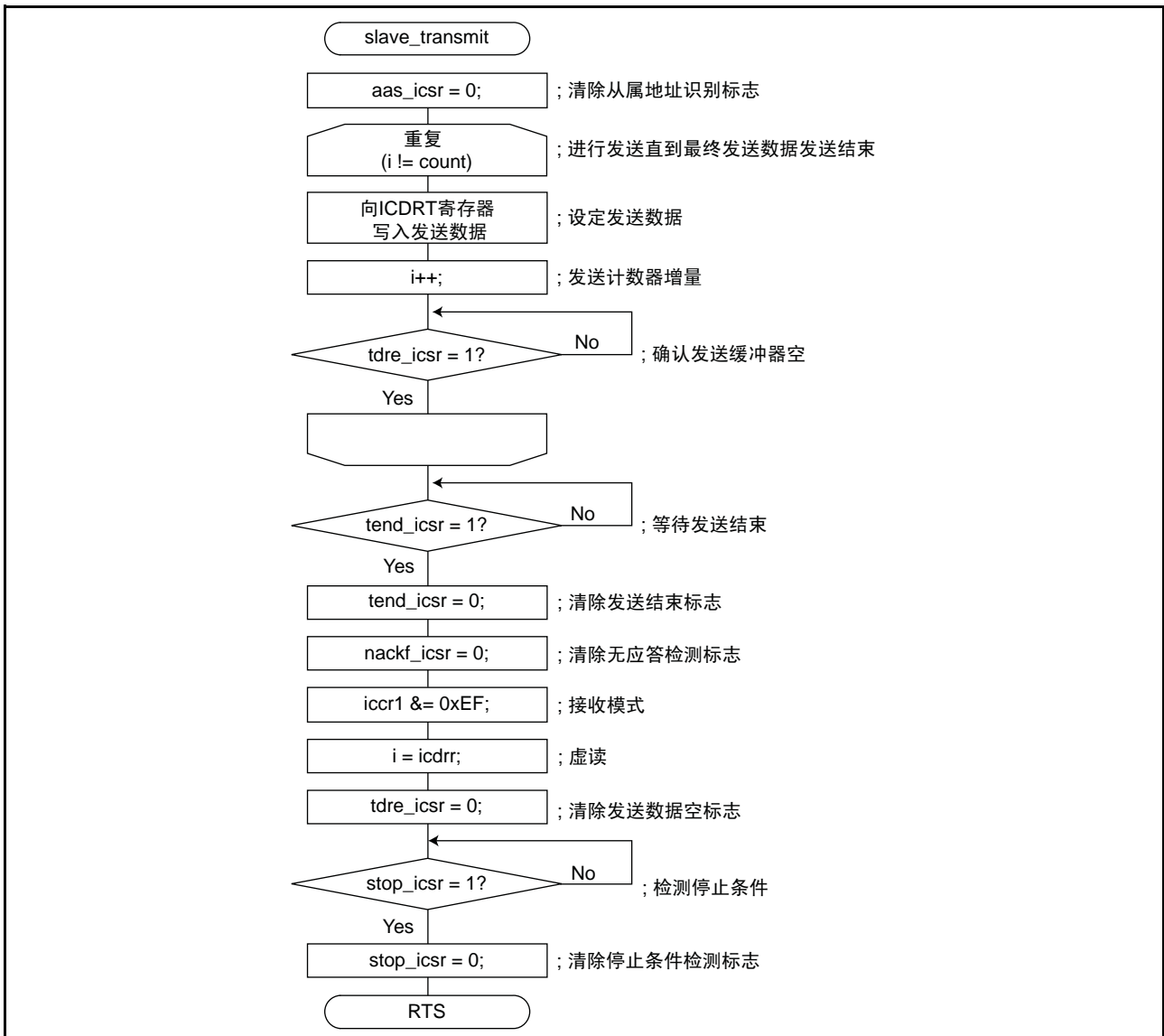
5.3.10 数据的接收



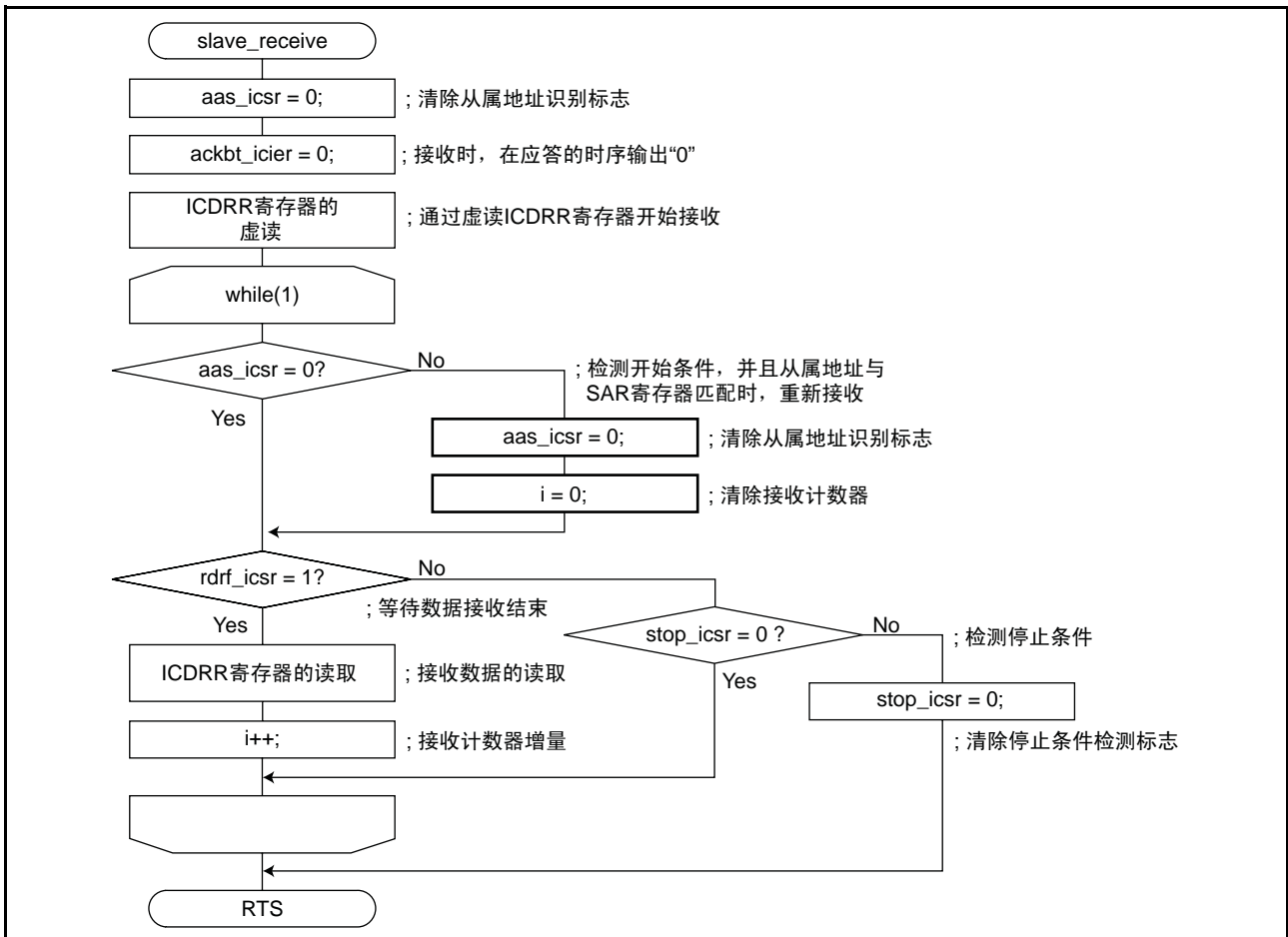
5.3.11 最终2字节数据的接收



5.3.12 从属发送



5.3.13 从属接收



6. 参考程序例

参考程序请从瑞萨科技公司主页获取。

请点击R8C/Tiny系列的首页画面左边菜单的“Application Notes”（应用说明）。

7. 参考文档

硬件手册

R8C/2D群硬件手册

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| Rev. | 发行日 | 修订内容 | |
|------|------------|------|------|
| | | 页 | 要点 |
| 1.00 | 2007.06.20 | — | 初版发行 |

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 - 2) 植埋于人体使用的装置。
 - 3) 用于治疗（切除患部、给药等）的装置。
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